Section I. Cyclone II Device Family Data Sheet

This section provides information for board layout designers to successfully layout their boards for Cyclone™ II devices. It contains the required PCB layout guidelines, device pin tables, and package specifications.

This section includes the following chapters:

Revision History

The table below shows the revision history for Chapters 1 through 6.

Chapter(s)	Date / Version	Changes Made
1	November 2004, v1.1	• Updated Table 1–2. • Updated bullet list in the "Features" section.
	June 2004, v1.0	Added document to the Cyclone II Device Handbook.
2	November 2004, v1.1	Updated Table 2–20.
	June 2004, v1.0	Added document to the Cyclone II Device Handbook.
3	November 2004. v1.1	Updated Table 3–4.
	June 2004, v1.0	Added document to the Cyclone II Device Handbook.
4	June 2004, v1.0	Added document to the Cyclone II Device Handbook.
5	November 2004, v1.1	• Updated the "Differential I/O Standards" section. • Updated Table 5–16.
	June 2004, v1.0	Added document to the Cyclone II Device Handbook.
6	November 2004, v1.1	Updated Figure 6–1.
	June 2004, v1.0	Added document to the Cyclone II Device Handbook.

Chapter 1. Introduction

CII51001-1.1

Introduction

Altera's low-cost Cyclone™ II FPGA family is based on a 1.2-V, 90-nm SRAM process with densities over 68K logic elements (LEs) and up to 1.1 Mbits of embedded RAM. With features like embedded 18 × 18 multipliers to support high-performance DSP applications, phase-locked loops (PLLs) for system clock management, and high-speed external memory interface support for SRAM and DRAM devices, Cyclone II devices are a cost-effective solution for high-volume applications. Cyclone II devices support differential and single-ended I/O standards, including LVDS at data rates up to 805 megabits per second (Mbps) for the receiver and 622 Mbps for the transmitter, and 64-bit, 66-MHz PCI and PCI-X for interfacing with processors and ASSP and ASIC devices. Altera also offers low-cost serial configuration devices to configure Cyclone II devices. The Cyclone II FPGA family offers commercial grade, industrial grade, and lead-free devices.

Features

The Cyclone II device family offers the following features:

- High-density architecture with 4,608 to 68,288 LEs
- M4K embedded memory blocks
  - Up to 1.1 Mbits of RAM available without reducing available logic
  - 4,096 memory bits per block (4,608 bits per block including 512 parity bits)
  - Variable port configurations of ×1, ×2, ×4, ×8, ×9, ×16, ×18, ×32, and ×36
  - True dual-port (one read and one write, two reads, or two writes) operation for ×1, ×2, ×4, ×8, ×9, ×16, and ×18 modes
  - Byte enables for data input masking during writes
  - Up to 250-MHz operation
- Embedded multipliers
  - 18- × 18-bit multipliers are each configurable as two independent 9- × 9-bit multipliers with up to 250-MHz performance
  - Optional input and output registers
- Advanced I/O support
  - High-speed differential I/O standard support, including LVDS, RSDS, mini-LVDS, LVPECL, differential HSTL, and differential SSTL
  - Single-ended I/O standard support, including 2.5-V and 1.8-V SSTL class I and II, 1.8-V and 1.5-V HSTL class I and II, 3.3-V PCI

and PCI-X 1.0, 3.3-, 2.5-, 1.8-, and 1.5-V LVCMOS, and 3.3-, 2.5-, and 1.8-V LVTTL
- Peripheral component interconnect Special Interest Group (PCI SIG) ***PCI Local Bus Specification, Revision 3.0*** compliance for 3.3-V operation at 33 or 66 MHz for 32- or 64-bit interfaces
- 100-MHz PCI-X 1.0 specification compatibility
- High-speed external memory support, including DDR, DDR2, and SDR SDRAM, and QDRII SRAM
- Three dedicated registers per I/O element (IOE): one input register, one output register, and one output-enable register
- Programmable bus-hold feature
- Programmable output drive strength feature
- Programmable delays from the pin to the IOE or logic array
- I/O bank grouping for unique V_{CCIO} and/or V_{REF} bank settings
- MultiVolt™ I/O standard support for 1.5-, 1.8-, 2.5-, and 3.3-V interfaces
- Hot-socketing operation support
- Tri-state with weak pull-up on I/O pins before and during configuration
- Programmable open-drain outputs
- Series on-chip termination support

■ Flexible clock management circuitry
- Hierarchical clock network for up to 402.5-MHz performance
- Up to four PLLs per device provide clock multiplication and division, phase shifting, programmable duty cycle, and external clock outputs, allowing system-level clock management and skew control
- Up to 16 global clock lines in the global clock network that drive throughout the entire device

■ Device configuration
- Fast serial configuration allows configuration times less than 100 ms
- Decompression feature allows for smaller programming file storage and faster configuration times
- Supports multiple configuration modes: active serial, passive serial, and JTAG-based configuration
- Supports configuration through low-cost serial configuration devices
- Device configuration supports multiple voltages (either 3.3, 2.5, or 1.8 V)

■ Intellectual property
- Altera megafunction support
- Altera MegaCore® function support
- Altera Megafunctions Partners Program (AMPPSM) megafunctions support

Table 1–1 lists the Cyclone II device family features. Table 1–2 lists the Cyclone II device package offerings and maximum user I/O pins.

Table 1–1. Cyclone II FPGA Family Features

Feature	EP2C5	EP2C8	EP2C20	EP2C35	EP2C50	EP2C70
LEs	4,608	8,256	18,752	33,216	50,528	68,416
M4K RAM blocks (4 Kbits plus 512 parity bits	26	36	52	105	129	250
Total RAM bits	119,808	165,888	239,616	483,840	594,432	1,152,000
Embedded multipliers *(1)*	13	18	26	35	86	150
PLLs	2	2	4	4	4	4
Maximum user I/O pins	142	182	315	475	450	622

Note to Table 1–1:

(1) This is the total number of 18 × 18 multipliers. For the total number of 9 × 9 multipliers per device, multiply the total number of 18 × 18 multipliers by 2.

Table 1–2. Cyclone II Package Options & Maximum User I/O Pins *Note (1)*

Device	144-Pin TQFP *(2)*	208-Pin PQFP *(3)*	256-Pin FineLine BGA	484-Pin FineLine BGA	672-Pin FineLine BGA	896-Pin FineLine BGA
EP2C5 *(5)*	89	142	*(4)*			
EP2C8 *(5)*	85	138	182			
EP2C20 *(5)*		*(4)*	152	315		
EP2C35 *(5)*				322	475	
EP2C50 *(5)*				294	450	
EP2C70 *(5)*					422	622

Notes to Table 1–2:

(1) Cyclone II devices support vertical migration within the same package (for example, designers can migrate between the EP2C20 device in the 484-pin FineLine BGA® package and the EP2C35 and EP2C50 devices in the same package).
(2) TQFP: thin quad flat pack.
(3) PQFP: plastic quad flat pack.
(4) Contact your local Altera sales representative for more information on this device.
(5) The I/O pin counts for the EP2C5 and EP2C8 devices include 8 dedicated clock pins that can be used for data inputs. The I/O counts for the EP2C20, EP2C35, EP2C50, and EP2C70 devices include 16 dedicated clock pins that can be used for data inputs.

Chapter 2. Cyclone II Architecture

CII51002-1.1

Functional Description

Cyclone™ II devices contain a two-dimensional row- and column-based architecture to implement custom logic. Column and row interconnects of varying speeds provide signal interconnects between logic array blocks (LABs), embedded memory blocks, and embedded multipliers.

The logic array consists of LABs, with 16 logic elements (LEs) in each LAB. An LE is a small unit of logic providing efficient implementation of user logic functions. LABs are grouped into rows and columns across the device. Cyclone II devices range in density from 4,608 to 68,416 LEs.

Cyclone II devices provide a global clock network and up to four phase-locked loops (PLLs). The global clock network consists of up to 16 global clock lines that drive throughout the entire device. The global clock network can provide clocks for all resources within the device, such as input/output elements (IOEs), LEs, embedded multipliers, and embedded memory blocks. The global clock lines can also be used for other high fan-out signals. Cyclone II PLLs provide general-purpose clocking with clock synthesis and phase shifting as well as external outputs for high-speed differential I/O support.

M4K memory blocks are true dual-port memory blocks with 4K bits of memory plus parity (4,608 bits). These blocks provide dedicated true dual-port, simple dual-port, or single-port memory up to 36-bits wide at up to 250 MHz. These blocks are arranged in columns across the device in between certain LABs. Cyclone II devices offer between 119 to 1,152 Kbits of embedded memory.

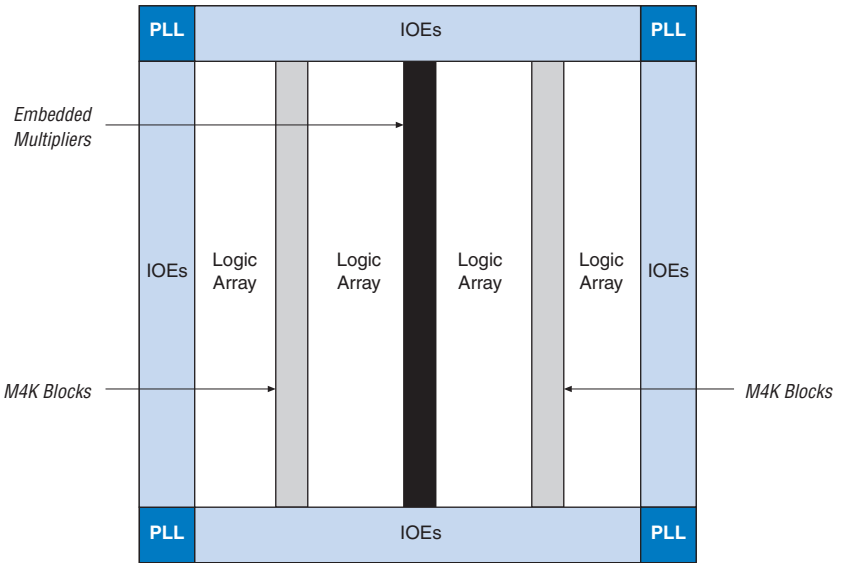
Each embedded multiplier block can implement up to either two 9 × 9-bit multipliers, or one 18 × 18-bit multiplier with up to 250-MHz performance. Embedded multipliers are arranged in columns across the device.

Each Cyclone II device I/O pin is fed by an IOE located at the ends of LAB rows and columns around the periphery of the device. I/O pins support various single-ended and differential I/O standards, such as the 66- and 33-MHz, 64- and 32-bit PCI standard, PCI-X, and the LVDS I/O standard at a maximum data rate of 805 megabits per second (Mbps) for inputs and 622 Mbps for outputs. Each IOE contains a bidirectional I/O buffer and three registers for registering input, output, and output-enable signals. Dual-purpose DQS, DQ, and DM pins along with delay chains (used to

phase-align double data rate (DDR) signals) provide interface support for external memory devices such as DDR, DDR2, and single data rate (SDR) SDRAM, and QDRII SRAM devices at up to 167 MHz.

Figure 2–1 shows a diagram of the Cyclone II EP2C20 device.

Figure 2–1. Cyclone II EP2C20 Device Block Diagram



The number of M4K memory blocks, embedded multiplier blocks, PLLs, rows, and columns vary per device. Table 2–1 lists the resources available in each Cyclone II device.

Table 2–1. Cyclone II Device Resources

Device	LAB Columns	LAB Rows	LEs	PLLs	M4K Memory Blocks	Embedded Multiplier Blocks
EP2C5	24	13	4,608	2	26	13
EP2C8	30	18	8,256	2	36	18
EP2C20	46	26	18,752	4	52	26
EP2C35	60	35	33,216	4	105	35
EP2C50	74	43	50,528	4	129	86
EP2C70	86	50	68,416	4	250	150

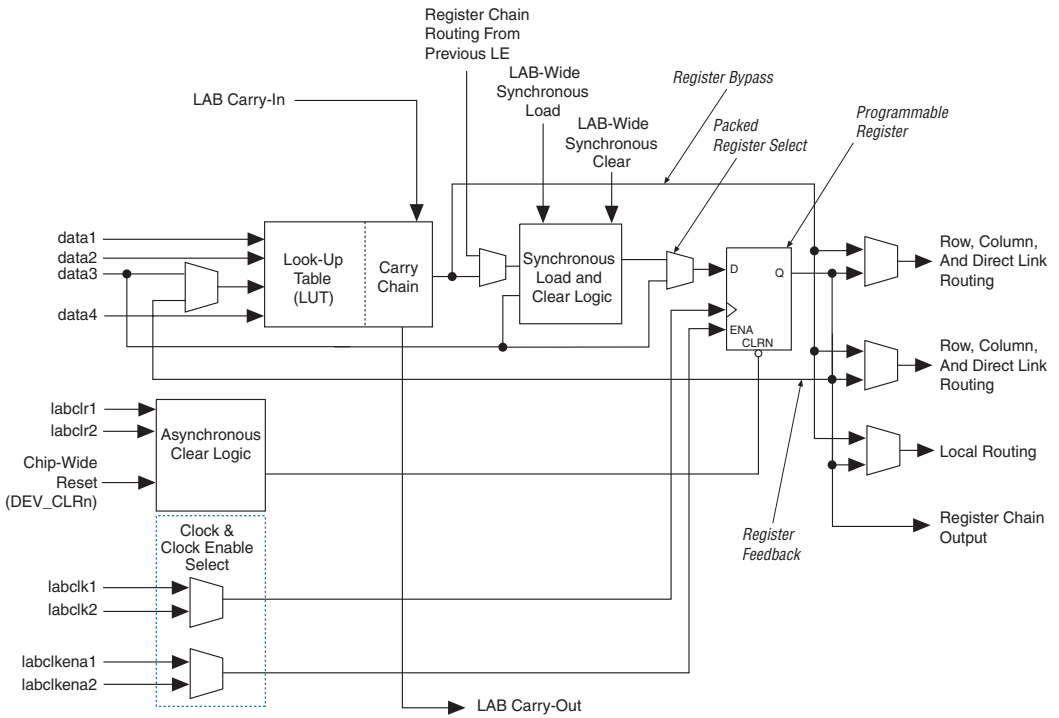
Logic Elements

The smallest unit of logic in the Cyclone II architecture, the LE, is compact and provides advanced features with efficient logic utilization. Each LE features:

- A four-input look-up table (LUT), which is a function generator that can implement any function of four variables
- A programmable register
- A carry chain connection
- A register chain connection
- The ability to drive all types of interconnects: local, row, column, register chain, and direct link interconnects
- Support for register packing
- Support for register feedback

Figure 2–2 shows a Cyclone II LE.

Figure 2–2. Cyclone II LE



Each LE's programmable register can be configured for D, T, JK, or SR operation. Each register has data, clock, clock enable, and clear inputs. Signals that use the global clock network, general-purpose I/O pins, or any internal logic can drive the register's clock and clear control signals. Either general-purpose I/O pins or internal logic can drive the clock enable. For combinatorial functions, the LUT output bypasses the register and drives directly to the LE outputs.

Each LE has three outputs that drive the local, row, and column routing resources. The LUT or register output can drive these three outputs independently. Two LE outputs drive column or row and direct link routing connections and one drives local interconnect resources, allowing the LUT to drive one output while the register drives another output. This feature, register packing, improves device utilization because the device can use the register and the LUT for unrelated functions. When using register packing, the LAB-wide synchronous load control signal is not available. See "LAB Control Signals" on page 2–8 for more information.

Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with its own fan-out LUT, providing another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

In addition to the three general routing outputs, the LEs within an LAB have register chain outputs. Register chain outputs allow registers within the same LAB to cascade together. The register chain output allows an LAB to use LUTs for a single combinatorial function and the registers to be used for an unrelated shift register implementation. These resources speed up connections between LABs while saving local interconnect resources. See "MultiTrack Interconnect" on page 2–10 for more information on register chain connections.

LE Operating Modes

The Cyclone II LE operates in one of the following modes:

- Normal mode
- Arithmetic mode

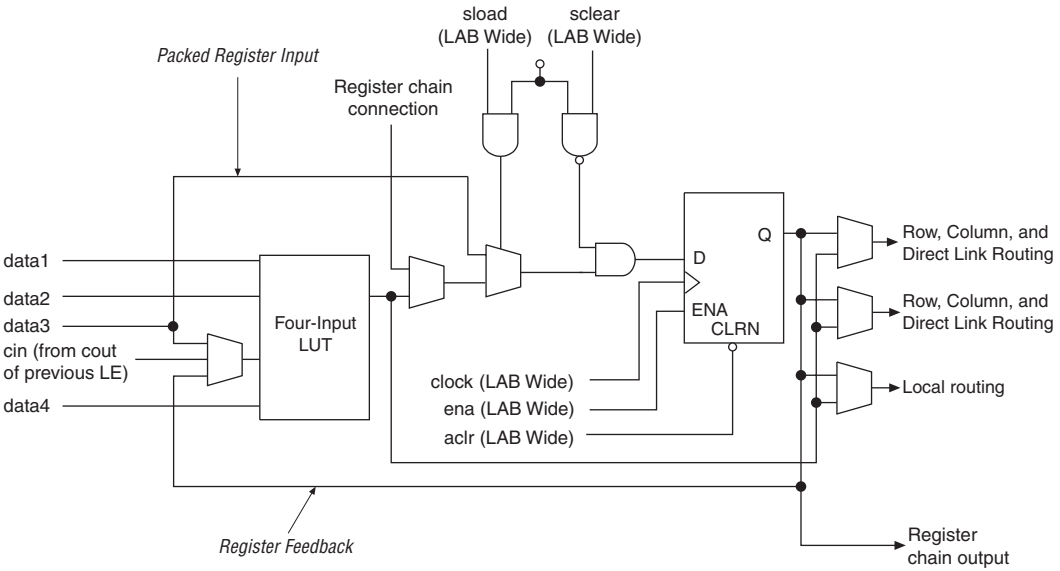
Each mode uses LE resources differently. In each mode, six available inputs to the LE—the four data inputs from the LAB local interconnect, the LAB carry-in from the previous carry-chain LAB, and the register chain connection—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear, synchronous clear, synchronous load, and clock enable control for the register. These LAB-wide signals are available in all LE modes.

The Quartus II software, in conjunction with parameterized functions such as library of parameterized modules (LPM) functions, automatically chooses the appropriate mode for common functions such as counters, adders, subtractors, and arithmetic functions. If required, the designer can also create special-purpose functions that specify which LE operating mode to use for optimal performance.

Normal Mode

The normal mode is suitable for general logic applications and combinatorial functions. In normal mode, four data inputs from the LAB local interconnect are inputs to a four-input LUT (see Figure 2–3). The Quartus II Compiler automatically selects the carry-in or the `data3` signal as one of the inputs to the LUT. LEs in normal mode support packed registers and register feedback.

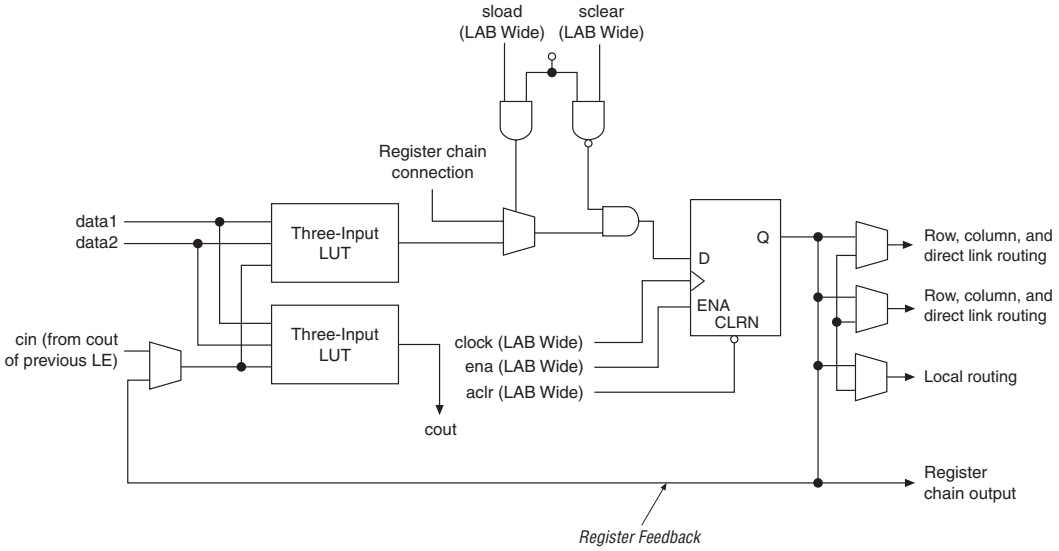
Figure 2–3. LE in Normal Mode



Arithmetic Mode

The arithmetic mode is ideal for implementing adders, counters, accumulators, and comparators. An LE in arithmetic mode implements a 2-bit full adder and basic carry chain (see Figure 2–4). LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output. Register feedback and register packing are supported when LEs are used in arithmetic mode.

Figure 2–4. LE in Arithmetic Mode



The Quartus II Compiler automatically creates carry chain logic during design processing, or the designer can create it manually during design entry. Parameterized functions such as LPM functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than 16 LEs by automatically linking LABs in the same column. For enhanced fitting, a long carry chain runs vertically, which allows fast horizontal connections to M4K memory blocks or embedded multipliers through direct link interconnects. For example, if a design has a long carry chain in a LAB column next to a column of M4K memory blocks, any LE output can feed an adjacent M4K memory block through the direct link interconnect. Whereas if the carry chains ran horizontally, any LAB not next to the column of M4K memory blocks would use other row or column interconnects to drive a M4K memory block. A carry chain continues as far as a full column.

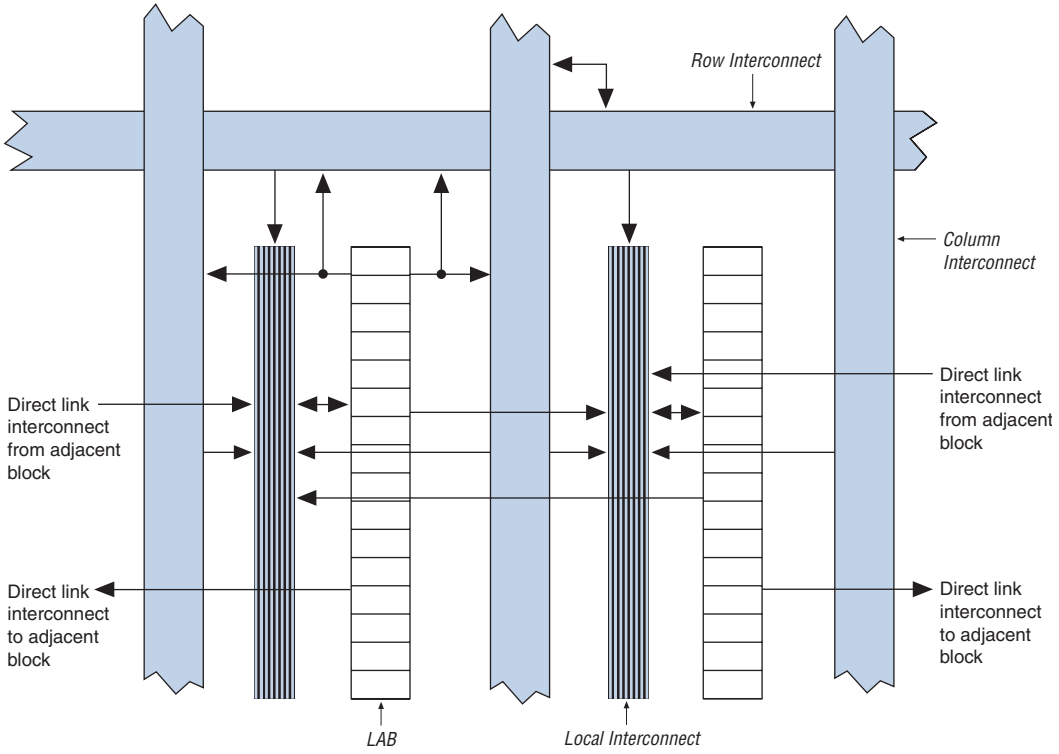
Logic Array Blocks

Each LAB consists of:

- 16 LEs
- LAB control signals
- LE carry chains
- Register chains
- Local interconnect

The local interconnect transfers signals between LEs in the same LAB. Register chain connections transfer the output of one LE's register to the adjacent LE's register within an LAB. The Quartus® II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of local, and register chain connections for performance and area efficiency. Figure 2–5 shows the Cyclone II LAB.

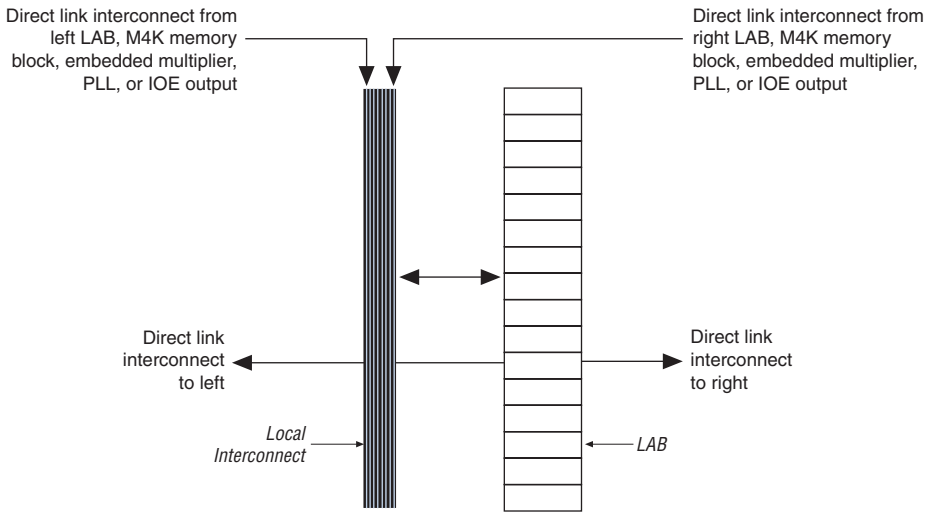
Figure 2–5. Cyclone II LAB Structure



LAB Interconnects

The LAB local interconnect can drive LEs within the same LAB. The LAB local interconnect is driven by column and row interconnects and LE outputs within the same LAB. Neighboring LABs, PLLs, M4K RAM blocks, and embedded multipliers from the left and right can also drive an LAB's local interconnect through the direct link connection. The direct link connection feature minimizes the use of row and column interconnects, providing higher performance and flexibility. Each LE can drive 48 LEs through fast local and direct link interconnects. Figure 2–6 shows the direct link connection.

Figure 2–6. Direct Link Connection



LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include:

- Two clocks
- Two clock enables
- Two asynchronous clears
- One synchronous clear
- One synchronous load

This gives a maximum of seven control signals at a time. When using the LAB-wide synchronous load, the `clkena` of `labclk1` is not available. Additionally, register packing and synchronous load cannot be used simultaneously.

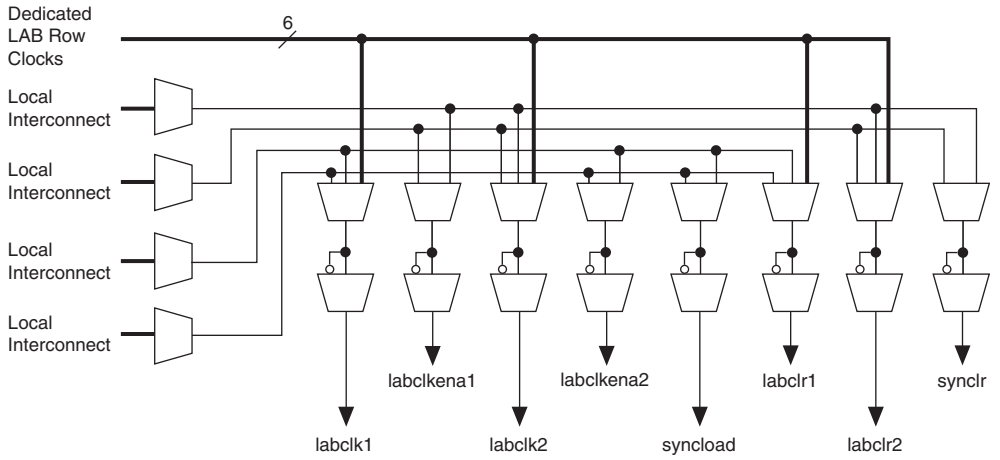
Each LAB can have up to four non-global control signals. Additional LAB control signals can be used as long as they are global signals.

Synchronous clear and load signals are useful for implementing counters and other functions. The synchronous clear and synchronous load signals are LAB-wide signals that affect all registers in the LAB.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked. For example, any LE in a particular LAB using the `labclk1` signal also uses `labclkena1`. If the LAB uses both the rising and falling edges of a clock, it also uses both LAB-wide clock signals. De-asserting the clock enable signal turns off the LAB-wide clock.

The LAB row clocks [5..0] and LAB local interconnect generate the LAB-wide control signals. The MultiTrack™ interconnect's inherent low skew allows clock and control signal distribution in addition to data. Figure 2–7 shows the LAB control signal generation circuit.

Figure 2–7. LAB-Wide Control Signals



LAB-wide signals control the logic for the register's clear signal. The LE directly supports an asynchronous clear function. Each LAB supports up to two asynchronous clear signals (`labclr1` and `labclr2`).

A LAB-wide asynchronous load signal to control the logic for the register's preset signal is not available. The register preset is achieved by using a NOT gate push-back technique. Cyclone II devices can only support either a preset or asynchronous clear signal.

In addition to the clear port, Cyclone II devices provide a chip-wide reset pin (DEV_CLRn) that resets all registers in the device. An option set before compilation in the Quartus II software controls this pin. This chip-wide reset overrides all other control signals.

MultiTrack Interconnect

In the Cyclone II architecture, connections between LEs, M4K memory blocks, embedded multipliers, and device I/O pins are provided by the MultiTrack interconnect structure with DirectDrive™ technology. The MultiTrack interconnect consists of continuous, performance-optimized routing lines of different speeds used for inter- and intra-design block connectivity. The Quartus II Compiler automatically places critical paths on faster interconnects to improve design performance.

DirectDrive technology is a deterministic routing technology that ensures identical routing resource usage for any function regardless of placement within the device. The MultiTrack interconnect and DirectDrive technology simplify the integration stage of block-based designing by eliminating the re-optimization cycles that typically follow design changes and additions.

The MultiTrack interconnect consists of row (direct link, R4, and R24) and column (register chain, C4, and C16) interconnects that span fixed distances. A routing structure with fixed-length resources for all devices allows predictable and repeatable performance when migrating through different device densities.

Row Interconnects

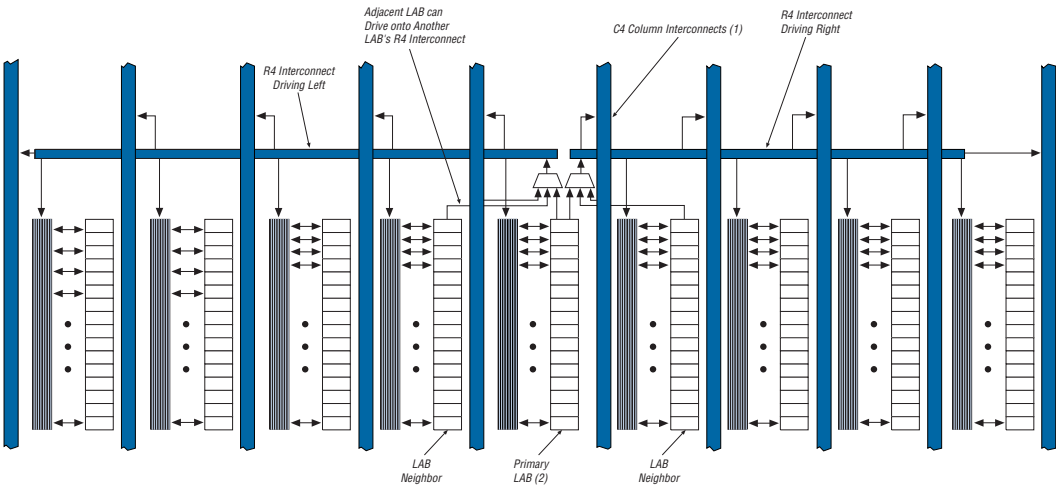
Dedicated row interconnects route signals to and from LABs, PLLs, M4K memory blocks, and embedded multipliers within the same row. These row resources include:

- Direct link interconnects between LABs and adjacent blocks
- R4 interconnects traversing four blocks to the right or left
- R24 interconnects for high-speed access across the length of the device

The direct link interconnect allows an LAB, M4K memory block, or embedded multiplier block to drive into the local interconnect of its left and right neighbors. Only one side of a PLL block interfaces with direct link and row interconnects. The direct link interconnect provides fast communication between adjacent LABs and/or blocks without using row interconnect resources.

The R4 interconnects span four LABs, three LABs and one M4K memory block, or three LABs and one embedded multiplier to the right or left of a source LAB. These resources are used for fast row connections in a four-LAB region. Every LAB has its own set of R4 interconnects to drive either left or right. Figure 2–8 shows R4 interconnect connections from an LAB. R4 interconnects can drive and be driven by LABs, M4K memory blocks, embedded multipliers, PLLs, and row IOEs. For LAB interfacing, a primary LAB or LAB neighbor (see Figure 2–8) can drive a given R4 interconnect. For R4 interconnects that drive to the right, the primary LAB and right neighbor can drive on to the interconnect. For R4 interconnects that drive to the left, the primary LAB and its left neighbor can drive on to the interconnect. R4 interconnects can drive other R4 interconnects to extend the range of LABs they can drive. Additionally, R4 interconnects can drive R24 interconnects, C4, and C16 interconnects for connections from one row to another.

Figure 2–8. R4 Interconnect Connections



Notes to Figure 2–8:

(1) C4 interconnects can drive R4 interconnects.

(2) This pattern is repeated for every LAB in the LAB row.

R24 row interconnects span 24 LABs and provide the fastest resource for long row connections between non-adjacent LABs, M4K memory blocks, dedicated multipliers, and row IOEs. R24 row interconnects drive to other row or column interconnects at every fourth LAB. R24 row interconnects drive LAB local interconnects via R4 and C4 interconnects and do not drive directly to LAB local interconnects. R24 interconnects can drive R24, R4, C16, and C4 interconnects.

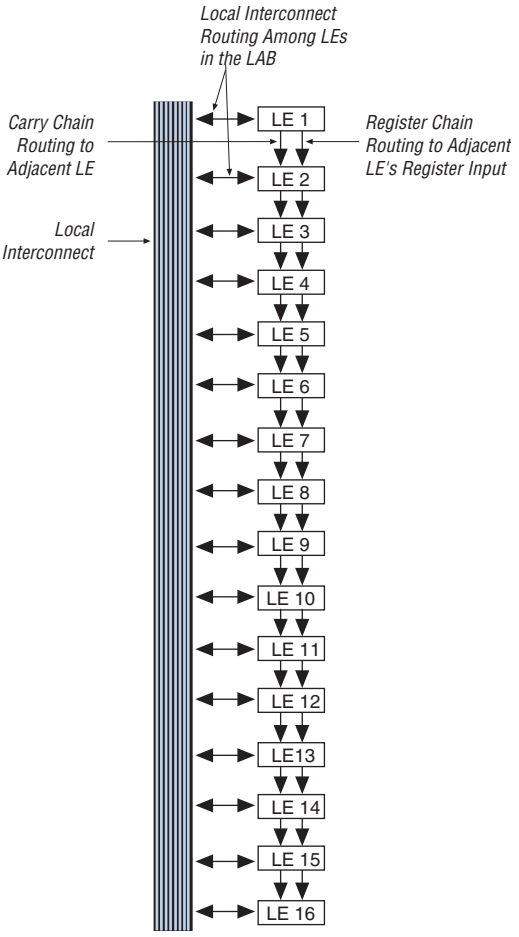
Column Interconnects

The column interconnect operates similar to the row interconnect. Each column of LABs is served by a dedicated column interconnect, which vertically routes signals to and from LABs, M4K memory blocks, embedded multipliers, and row and column IOEs. These column resources include:

- Register chain interconnects within an LAB
- C4 interconnects traversing a distance of four blocks in an up and down direction
- C16 interconnects for high-speed vertical routing through the device

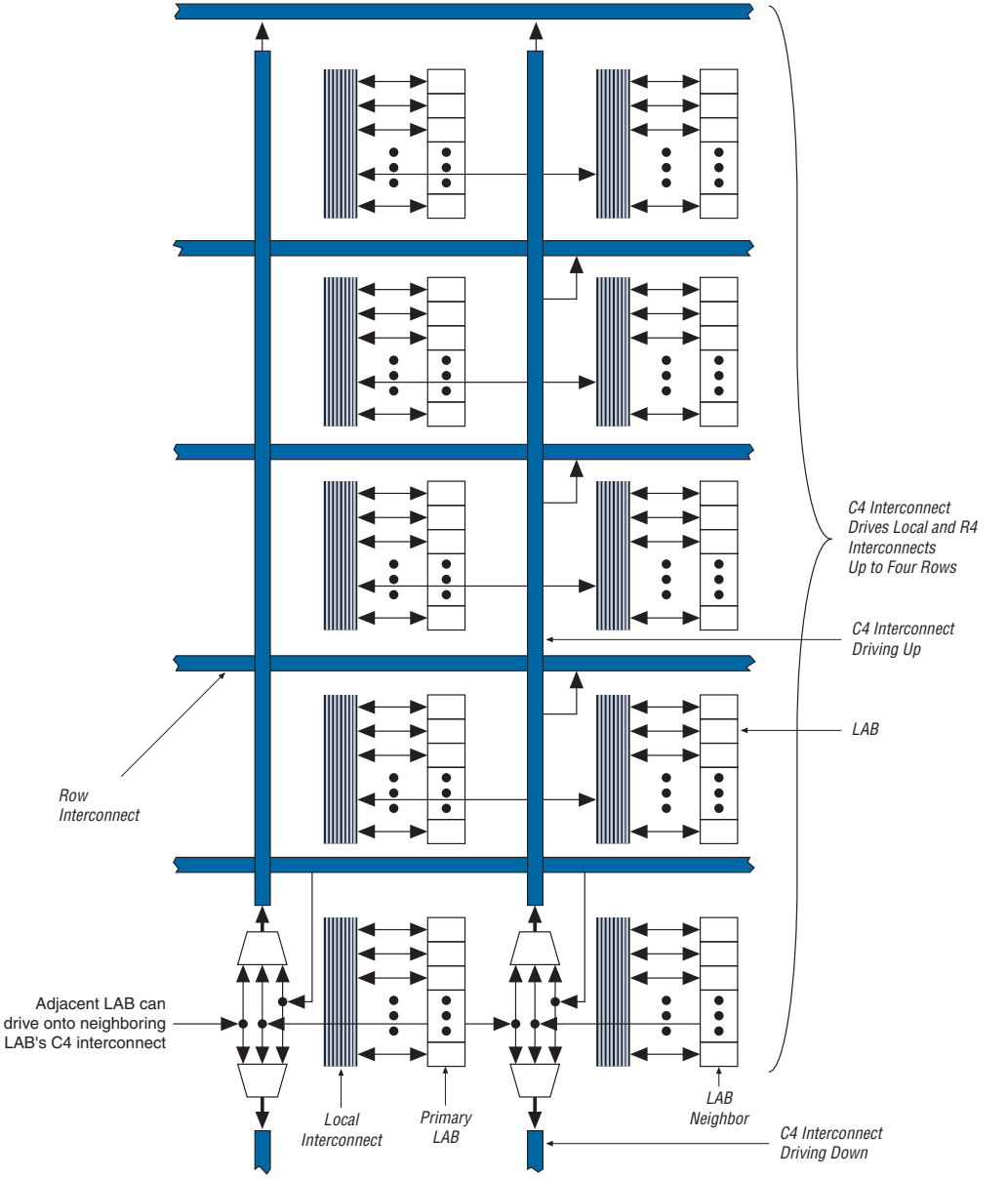
Cyclone II devices include an enhanced interconnect structure within LABs for routing LE output to LE input connections faster using register chain connections. The register chain connection allows the register output of one LE to connect directly to the register input of the next LE in the LAB for fast shift registers. The Quartus II Compiler automatically takes advantage of these resources to improve utilization and performance. Figure 2–9 shows the register chain interconnects.

Figure 2–9. Register Chain Interconnects



The C4 interconnects span four LABs, M4K blocks, or embedded multipliers up or down from a source LAB. Every LAB has its own set of C4 interconnects to drive either up or down. Figure 2–10 shows the C4 interconnect connections from an LAB in a column. The C4 interconnects can drive and be driven by all types of architecture blocks, including PLLs, M4K memory blocks, embedded multiplier blocks, and column and row IOEs. For LAB interconnection, a primary LAB or its LAB neighbor (see Figure 2–10) can drive a given C4 interconnect. C4 interconnects can drive each other to extend their range as well as drive row interconnects for column-to-column connections.

Figure 2–10. C4 Interconnect Connections *Note (1)*



Note to Figure 2–10:
(1) Each C4 interconnect can drive either up or down four rows.

C16 column interconnects span a length of 16 LABs and provide the fastest resource for long column connections between LABs, M4K memory blocks, embedded multipliers, and IOEs. C16 column interconnects drive to other row and column interconnects at every fourth LAB. C16 column interconnects drive LAB local interconnects via C4 and R4 interconnects and do not drive LAB local interconnects directly. C16 interconnects can drive R24, R4, C16, and C4 interconnects.

Device Routing

All embedded blocks communicate with the logic array similar to LAB-to-LAB interfaces. Each block (for example, M4K memory, embedded multiplier, or PLL) connects to row and column interconnects and has local interconnect regions driven by row and column interconnects. These blocks also have direct link interconnects for fast connections to and from a neighboring LAB.

Table 2–2 shows the Cyclone II device's routing scheme.

Table 2–2. Cyclone II Device Routing Scheme (Part 1 of 2)

Source	Destination												
	Register Chain	Local Interconnect	Direct Link Interconnect	R4 Interconnect	R24 Interconnect	C4 Interconnect	C16 Interconnect	LE	M4K RAM Block	Embedded Multiplier	PLL	Column IOE	Row IOE
Register Chain								✓					
Local Interconnect								✓	✓	✓	✓	✓	✓
Direct Link Interconnect		✓											
R4 Interconnect		✓		✓	✓	✓	✓						
R24 Interconnect				✓	✓	✓	✓						
C4 Interconnect		✓		✓	✓	✓	✓						
C16 Interconnect				✓	✓	✓	✓						

Table 2–2. Cyclone II Device Routing Scheme (Part 2 of 2)

Source	Destination												
	Register Chain	Local Interconnect	Direct Link Interconnect	R4 Interconnect	R24 Interconnect	C4 Interconnect	C16 Interconnect	LE	M4K RAM Block	Embedded Multiplier	PLL	Column IOE	Row IOE
LE	✓	✓	✓	✓		✓							
M4K memory Block		✓	✓	✓		✓							
Embedded Multipliers		✓	✓	✓		✓							
PLL			✓	✓		✓							
Column IOE						✓	✓						
Row IOE			✓	✓	✓	✓							

Global Clock Network & Phase-Locked Loops

Cyclone II devices provide global clock networks and up to four PLLs for a complete clock management solution. Cyclone II clock network features include:

- Up to 16 global clock networks
- Up to four PLLs
- Global clock network dynamic clock source selection
- Global clock network dynamic enable and disable

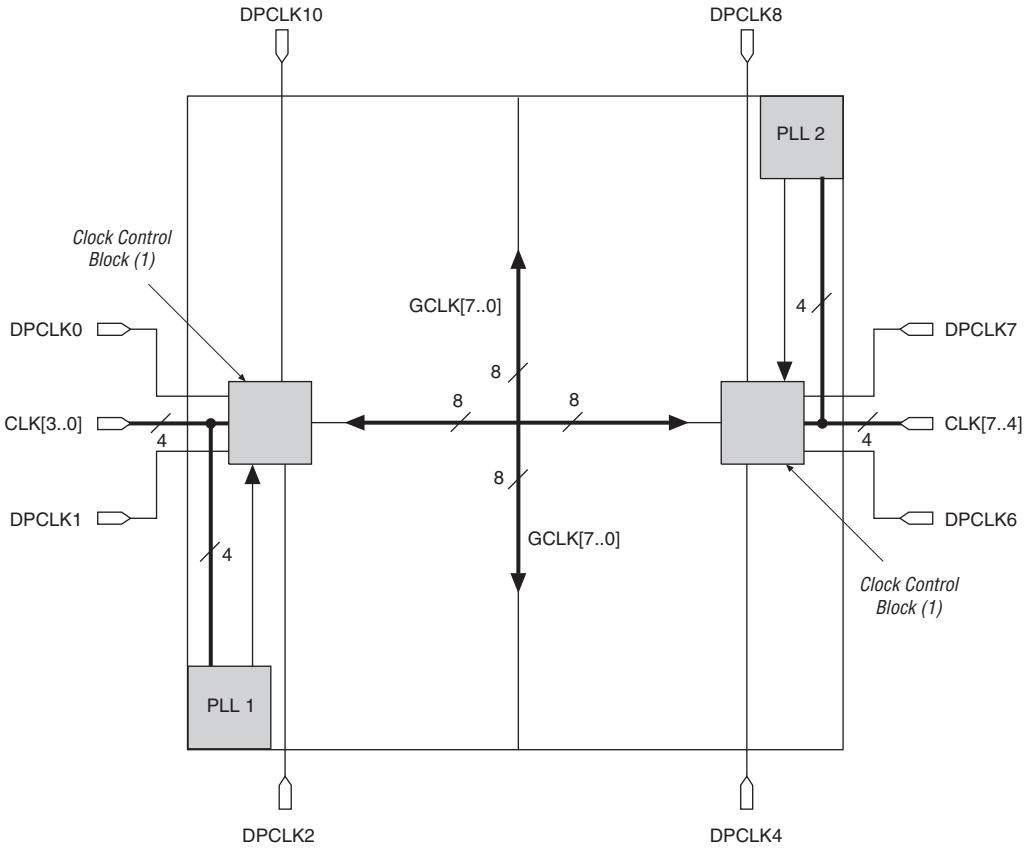
Each global clock network has a clock control block to select from a number of input clock sources (PLL clock outputs, CLK[] pins, DPCLK[] pins, and internal logic) to drive onto the global clock network. Table 2–3 lists how many PLLs, CLK[] pins, DPCLK[] pins, and global clock networks are available in each Cyclone II device. CLK[] pins are dedicated clock pins and DPCLK[] pins are dual-purpose clock pins.

Table 2–3. Cyclone II Device Clock Resources

Device	Number of PLLs	Number of CLK Pins	Number of DPCLK Pins	Number of Global Clock Networks
EP2C5	2	8	8	8
EP2C8	2	8	8	8
EP2C20	4	16	20	16
EP2C35	4	16	20	16
EP2C50	4	16	20	16
EP2C70	4	16	20	16

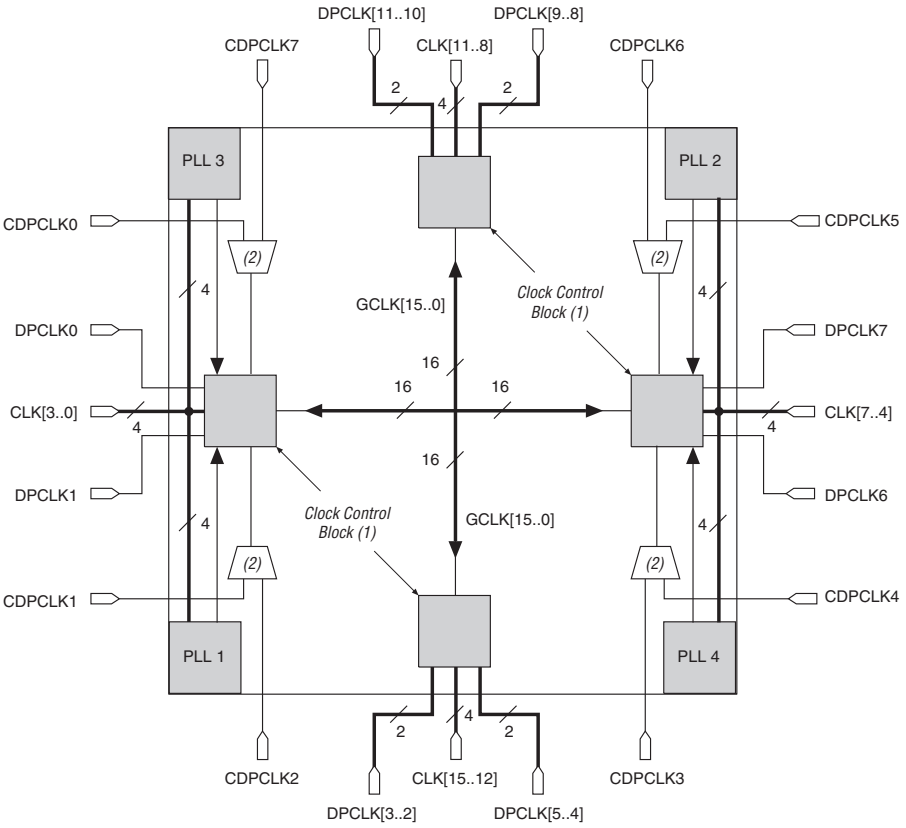
Figures 2–11 and 2–12 show the location of the Cyclone II PLLs, CLK[] inputs, DPCLK[] pins, and clock control blocks.

Figure 2–11. EP2C5 & EP2C8 PLL, CLK[], DPCLK[] & Clock Control Block Locations



Note to Figure 2–11:
(1) There are four clock control blocks on each side.

Figure 2–12. EP2C20 & Larger PLL, CLK[], DPCLK[] & Clock Control Block Locations



Notes to Figure 2–12:

(1) There are four clock control blocks on each side.

(2) Only one of the corner CDPCLK pins in each corner can feed the clock control block at a time. The other CDPCLK pins can be used as general-purpose I/O pins.

Dedicated Clock Pins

Larger Cyclone II devices (EP2C20 and larger devices) have 16 dedicated clock pins (CLK[15..0], four pins on each side of the device). Smaller Cyclone II devices (EP2C5 and EP2C8 devices) have eight dedicated clock pins (CLK[7..0], four pins on left and right sides of the device). These CLK pins drive the global clock network (GCLK), as shown in Figures 2–11 and 2–12.

If the dedicated clock pins are not used to feed the global clock networks, they can be used as general-purpose input pins to feed the logic array using the MultiTrack interconnect. However, if they are used as general-purpose input pins, they do not have support for an I/O register and must use LE-based registers in place of an I/O register.

Dual-Purpose Clock Pins

Cyclone II devices have either 20 dual-purpose clock pins, DPCLK[19..0] or 8 dual-purpose clock pins, DPCLK[7..0]. In the larger Cyclone II devices (EP2C20 devices and higher), there are 20 DPCLK pins; four on the left and right sides and six on the top and bottom of the device. The corner CDPCLK pins are first multiplexed before they drive into the clock control block. Since the signals pass through a multiplexer before feeding the clock control block, these signals incur more delay to the clock control block than other DPCLK pins that directly feed the clock control block. In the smaller Cyclone II devices (EP2C5 and EP2C8 devices), there are eight DPCLK pins; two on each side of the device (see Figures 2–11 and 2–12).

A programmable delay chain is available from the DPCLK pin to its fan-out destinations. To set the propagation delay from the DPCLK pin to its fan-out destinations, use the **Input Delay from Dual-Purpose Clock Pin to Fan-Out Destinations** assignment in the Quartus II software.

These dual-purpose pins can connect to the global clock network for high-fanout control signals such as clocks, asynchronous clears, presets, and clock enables, or protocol control signals such as TRDY and IRDY for PCI, or DQS signals for external memory interfaces.

Global Clock Network

The 16 or 8 global clock networks drive throughout the entire device. Dedicated clock pins (CLK[]), PLL outputs, the logic array, and dual-purpose clock (DPCLK[]) pins can also drive the global clock network.

The global clock network can provide clocks for all resources within the device, such as IOEs, LEs, memory blocks, and embedded multipliers. The global clock lines can also be used for control signals, such as clock enables and synchronous or asynchronous clears fed from the external pin, or DQS signals for DDR SDRAM or QDRII SRAM interfaces. Internal logic can also drive the global clock network for internally generated global clocks and asynchronous clears, clock enables, or other control signals with large fan-out.

Clock Control Block

There is a clock control block for each global clock network available in Cyclone II devices. The clock control blocks are arranged on the device periphery and there are a maximum of 16 clock control blocks available per Cyclone II device. The larger Cyclone II devices (EP2C20 devices and larger) have 16 clock control blocks, four on each side of the device. The smaller Cyclone II devices (EP2C5 and EP2C8 devices) have eight clock control blocks, four on the left and right sides of the device.

The control block has these functions:

- Dynamic global clock network clock source selection
- Dynamic enable/disable of the global clock network

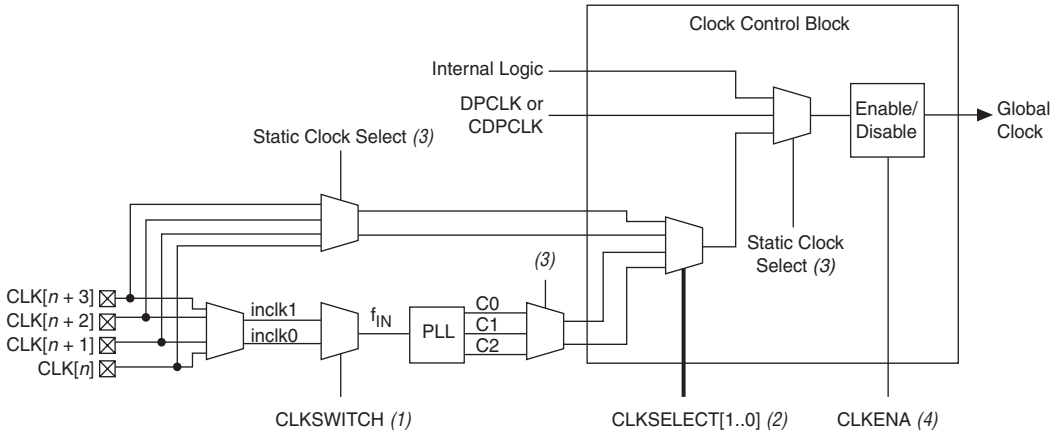
In Cyclone II devices, the dedicated CLK[] pins, PLL counter outputs, DPCLK[] pins, and internal logic can all feed the clock control block. The output from the clock control block in turn feeds the corresponding global clock network.

The following sources can be inputs to a given clock control block:

- Four clock pins on the same side as the clock control block
- Three PLL clock outputs from a PLL
- Four DPCLK pins (including CDPCLK pins) on the same side as the clock control block
- Four internally-generated signals

Of the sources listed, only two clock pins, two PLL clock outputs, one DPCLK pin, and one internally-generated signal are chosen to drive into a clock control block. Figure 2–13 shows a more detailed diagram of the clock control block. Out of these six inputs, the two clock input pins and two PLL outputs can be dynamic selected to feed a global clock network. The clock control block supports static selection of DPCLK and the signal from internal logic.

Figure 2–13. Clock Control Block



Notes to Figure 2–13:

(1) The CLKSWITCH signal can either be set through the configuration file or it can be dynamically set when using the manual PLL switchover feature. The output of the multiplexer is the input reference clock (f_{IN}) for the PLL.

(2) The CLKSELECT[1..0] signals are fed by internal logic and can be used to dynamically select the clock source for the global clock network when the device is in user mode.

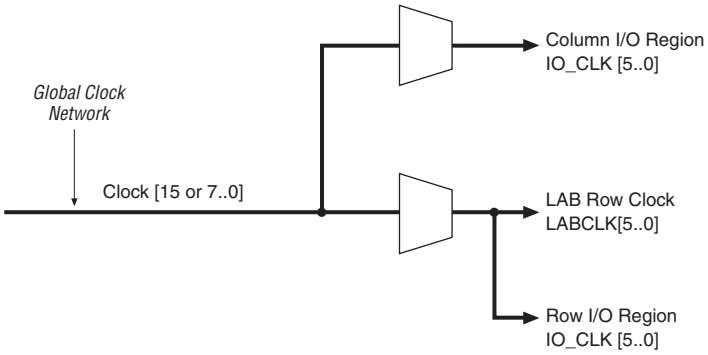
(3) The static clock select signals are set in the configuration file and cannot be dynamically controlled when the device is in user mode.

(4) Internal logic can be used to enabled or disabled the global clock network in user mode.

Global Clock Network Distribution

Cyclone II devices contains 16 global clock networks. The device uses multiplexers with these clocks to form six-bit buses to drive column IOE clocks, LAB row clocks, or row IOE clocks (see Figure 2–14). Another multiplexer at the LAB level selects two of the six LAB row clocks to feed the LE registers within the LAB.

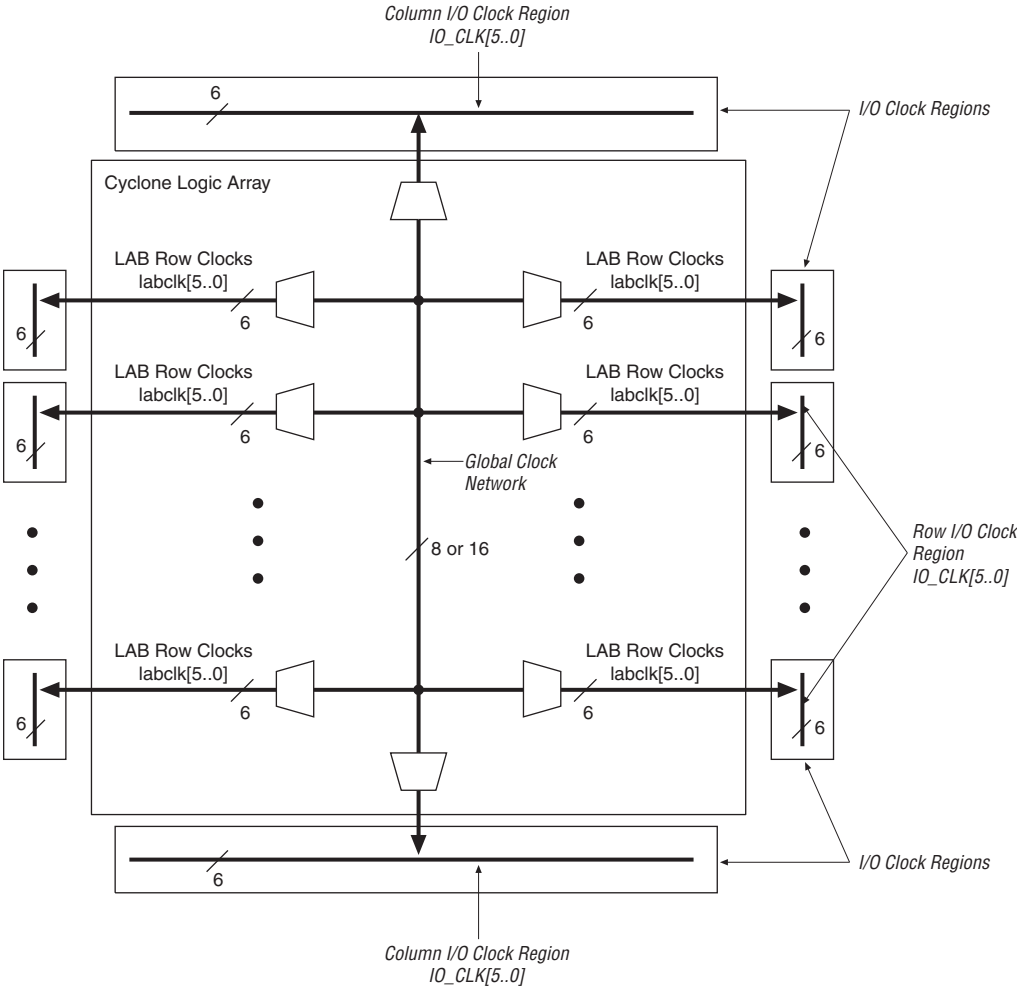
Figure 2–14. Global Clock Network Multiplexers



LAB row clocks can feed LEs, M4K memory blocks, and embedded multipliers. The LAB row clocks also extend to the row I/O clock regions.

IOE clocks are associated with row or column block regions. Only six global clock resources feed to these row and column regions. Figure 2–15 shows the I/O clock regions.

Figure 2–15. LAB & I/O Clock Regions



For more information on the global clock network and the clock control block, see the *PLLs in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

PLLs

Cyclone II PLLs provide general-purpose clocking as well as support for the following features:

- Clock multiplication and division
- Phase shifting
- Programmable duty cycle
- Up to three internal clock outputs
- One dedicated external clock output
- Clock outputs for differential I/O support
- Manual clock switchover
- Programmable bandwidth
- Gated lock signal
- Three different clock feedback modes
- Control signals

Cyclone II devices contain either two or four PLLs. Table 2–4 shows the PLLs available for each Cyclone II device.

Table 2–4. Cyclone II Device PLL Availability

Device	PLL1	PLL2	PLL3	PLL4
EP2C5	✓	✓		
EP2C8	✓	✓		
EP2C20	✓	✓	✓	✓
EP2C35	✓	✓	✓	✓
EP2C50	✓	✓	✓	✓
EP2C70	✓	✓	✓	✓

Table 2–5 describes the PLL features in Cyclone II devices.

Table 2–5. Cyclone II PLL Features (Part 1 of 2)

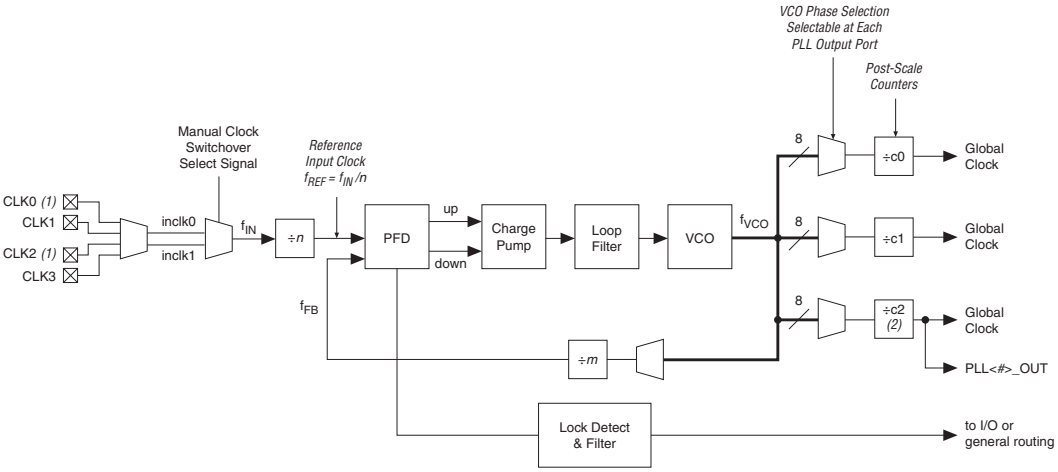
Feature	Description
Clock multiplication and division	*m* / (*n* × post-scale counter) *m* and post-scale counter values (C0 to C2) range from 1 to 32. *n* ranges from 1 to 4.
Phase shift	Cyclone II PLLs have an advanced clock shift capability that enables programmable phase shifts in increments of at least 45°. The finest resolution of phase shifting is determined by the voltage control oscillator (VCO) period divided by 8 (for example, 1/1000 MHz/8 = down to 125-ps increments).

Table 2–5. Cyclone II PLL Features (Part 2 of 2)

Feature	Description
Programmable duty cycle	The programmable duty cycle allows PLLs to generate clock outputs with a variable duty cycle. This feature is supported on each PLL post-scale counter (C0-C2).
Number of internal clock outputs	The Cyclone II PLL has three outputs which can drive the global clock network. One of these outputs (C2) can also drive a dedicated PLL<#>_OUT pin (single ended or differential).
Number of external clock outputs	The C2 output drives a dedicated PLL<#>_OUT pin. If the C2 output is not used to drive an external clock output, it can be used to drive the internal global clock network. The C2 output can concurrently drive the external clock output and internal global clock network.
Manual clock switchover	The Cyclone II PLLs support manual switchover of the reference clock through internal logic. This enables a designer to switch between two reference input clocks during user mode for applications that may require clock redundancy or support for clocks with two different frequencies.
Programmable bandwidth	Cyclone II PLLs allow the designer to control the bandwidth over a finite range to customize the PLL characteristics for a particular application. Advanced control of the PLL bandwidth is provided through the programmable characteristics of the PLL loop, including loop filter and charge pump. The bandwidth range is determined after characterization.
Gated lock signal	The lock output indicates that there is a stable clock output signal in phase with the reference clock. Cyclone II PLLs include a programmable counter that holds the lock signal low for a user-selected number of input clock transitions, allowing the PLL to lock before enabling the locked signal. Either a gated locked signal or an ungated locked signal from the locked port can drive internal logic or an output pin.
Clock feedback modes	In zero delay buffer mode, the external clock output pin is phase-aligned with the clock input pin for zero delay. In normal mode, the PLL compensates for the internal global clock network delay from the input clock pin to the clock port of the IOE output registers or registers in the logic array. In no compensation mode, the PLL does not compensate for any clock networks.
Control signals	The pllenable signal enables and disables the PLLs. The areset signal resets/resynchronizes the inputs for each PLL. The pfdena signal controls the phase frequency detector (PFD) output with a programmable gate.

Figure 2–16 shows a block diagram of the Cyclone II PLL.

Figure 2–16. Cyclone II PLL *Note (1)*



Notes to Figure 2–16:

(1) This input can be single-ended or differential. If a designer is using a differential I/O standard, then two CLK pins are used. LVDS input is supported via the secondary function of the dedicated CLK pins. For example, the CLK0 pin's secondary function is LVDSCLK1p and the CLK1 pin's secondary function is LVDSCLK1n. If a differential I/O standard is assigned to the PLL clock input pin, the corresponding CLK(n) pin is also completely used. The Figure 2–16 shows the possible clock input connections (CLK0/CLK1) to PLL1.

(2) This counter output is shared between a dedicated external clock output I/O and the global clock network.

For more information on Cyclone II PLLs, see the PLLs in the *Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Embedded Memory

The Cyclone II embedded memory consists of columns of M4K memory blocks. The M4K memory blocks include input registers that synchronize writes and output registers to pipeline designs and improve system performance. The output registers can be bypassed, but input registers cannot.

Each M4K block can implement various types of memory with or without parity, including true dual-port, simple dual-port, and single-port RAM, ROM, and first-in first-out (FIFO) buffers. The M4K blocks support the following features:

- 4,608 RAM bits
- 250-MHz performance
- True dual-port memory
- Simple dual-port memory
- Single-port memory
- Byte enable
- Parity bits
- Shift register
- FIFO buffer
- ROM
- Various clock modes
- Address clock enable

Table 2–6 shows the capacity and distribution of the M4K memory blocks in each Cyclone II device.

Table 2–6. M4K Memory Capacity & Distribution in Cyclone II Devices

Device	M4K Columns	M4K Blocks	Total RAM Bits
EP2C5	2	26	119,808
EP2C8	2	36	165,888
EP2C20	2	52	239,616
EP2C35	3	105	483,840
EP2C50	3	129	594,432
EP2C70	5	250	1,152,000

Table 2–7 summarizes the features supported by the M4K memory.

Table 2–7. M4K Memory Features (Part 1 of 2)

Feature	Description
Maximum performance *(1)*	250 MHz
Total RAM bits per M4K block (including parity bits)	4,608

Table 2–7. M4K Memory Features (Part 2 of 2)

Feature	Description
Configurations supported	4K × 1 2K × 2 1K × 4 512 × 8 512 × 9 256 × 16 256 × 18 128 × 32 (not available in true dual-port mode) 128 × 36 (not available in true dual-port mode)
Parity bits	One parity bit for each byte. The parity bit, along with internal user logic, can implement parity checking for error detection to ensure data integrity.
Byte enable	M4K blocks support byte writes when the write port has a data width of 1, 2, 4, 8, 9, 16, 18, 32, or 36 bits. The byte enables allow the input data to be masked so the device can write to specific bytes. The unwritten bytes retain the previous written value.
Packed mode	Two single-port memory blocks can be packed into a single M4K block if each of the two independent block sizes are equal to or less than half of the M4K block size, and each of the single-port memory blocks is configured in single-clock mode.
Address clock enable	M4K blocks support address clock enable, which is used to hold the previous address value for as long as the signal is enabled. This feature is useful in handling misses in cache applications.
Memory initialization file (**.mif**)	When configured as RAM or ROM, the designer can use an initialization file to pre-load the memory contents.
Power-up condition	Outputs cleared
Register clears	Output registers only
Same-port read-during-write	New data available at positive clock edge
Mixed-port read-during-write	Old data available at positive clock edge

Note to Table 2–7:
(1) Maximum performance information is preliminary until device characterization.

Memory Modes

Table 2–8 summarizes the different memory modes supported by the M4K memory blocks.

Table 2–8. M4K Memory Modes

Memory Mode	Description
Single-port memory	M4K blocks support single-port mode, used when simultaneous reads and writes are not required. Single-port memory supports non-simultaneous reads and writes.
Simple dual-port memory	Simple dual-port memory supports a simultaneous read and write.
Simple dual-port with mixed width	Simple dual-port memory mode with different read and write port widths.
True dual-port memory	True dual-port mode supports any combination of two-port operations: two reads, two writes, or one read and one write at two different clock frequencies.
True dual-port with mixed width	True dual-port mode with different read and write port widths.
Embedded shift register	M4K memory blocks are used to implement shift registers. Data is written into each address location at the falling edge of the clock and read from the address at the rising edge of the clock.
ROM	The M4K memory blocks support ROM mode. A MIF initializes the ROM contents of these blocks.
FIFO buffers	A single clock or dual clock FIFO may be implemented in the M4K blocks. Simultaneous read and write from an empty FIFO buffer is not supported.

Clock Modes

Table 2–9 summarizes the different clock modes supported by the M4K memory.

Table 2–9. M4K Clock Modes

Clock Mode	Description
Independent	In this mode, a separate clock is available for each port (ports A and B). Clock A controls all registers on the port A side, while clock B controls all registers on the port B side.
Input/output	On each of the two ports, A or B, one clock controls all registers for inputs into the memory block: data input, `wren`, and address. The other clock controls the block's data output registers.
Read/write	Up to two clocks are available in this mode. The write clock controls the block's data inputs, `wraddress`, and `wren`. The read clock controls the data output, `rdaddress`, and `rden`.
Single	In this mode, a single clock, together with clock enable, is used to control all registers of the memory block. Asynchronous clear signals for the registers are not supported.

Table 2–10 shows which clock modes are supported by all M4K blocks when configured in the different memory modes.

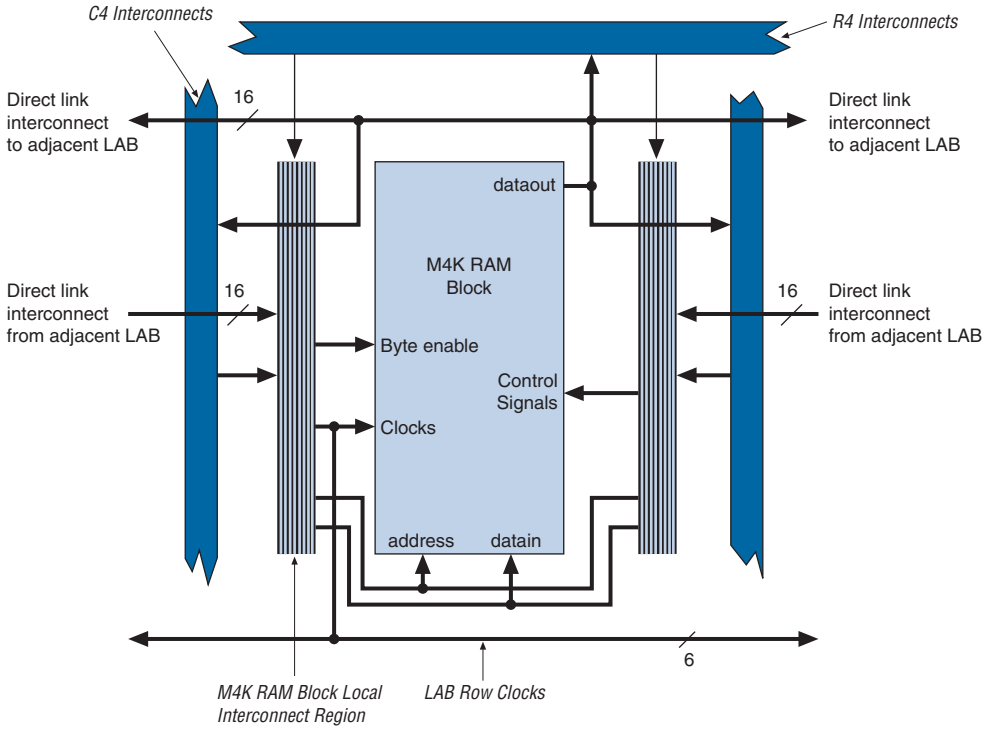
Table 2–10. Cyclone II M4K Memory Clock Modes

Clocking Modes	True Dual-Port Mode	Simple Dual-Port Mode	Single-Port Mode
Independent	✓		
Input/output	✓	✓	✓
Read/write		✓	
Single clock	✓	✓	✓

M4K Routing Interface

The R4, C4, and direct link interconnects from adjacent LABs drive the M4K block local interconnect. The M4K blocks can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 16 direct link input connections to the M4K block are possible from the left adjacent LAB and another 16 possible from the right adjacent LAB. M4K block outputs can also connect to left and right LABs through each 16 direct link interconnects. Figure 2–17 shows the M4K block to logic array interface.

Figure 2–17. M4K RAM Block LAB Row Interface



For more information on Cyclone II embedded memory, see the *Cyclone II Memory Blocks* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Embedded Multipliers

Cyclone II devices have embedded multiplier blocks optimized for multiplier-intensive digital signal processing (DSP) functions, such as finite impulse response (FIR) filters, fast Fourier transform (FFT) functions, and discrete cosine transform (DCT) functions. Designers can use the embedded multiplier in one of two basic operational modes, depending on the application needs:

- One 18-bit multiplier
- Up to two independent 9-bit multipliers

Embedded multipliers can operate at up to 250 MHz (for the fastest speed grade) for 18 × 18 and 9 × 9 multiplications when using both input and output registers.

Each Cyclone II device has one to three columns of embedded multipliers that efficiently implement multiplication functions. An embedded multiplier spans the height of one LAB row. Table 2–11 shows the number of embedded multipliers in each Cyclone II device and the multipliers that can be implemented.

Table 2–11. Number of Embedded Multipliers in Cyclone II Devices *Note (1)*

Device	Embedded Multiplier Columns	Embedded Multipliers	9 × 9 Multipliers	18 × 18 Multipliers
EP2C5	1	13	26	13
EP2C8	1	18	36	18
EP2C20	1	26	52	26
EP2C35	1	35	70	35
EP2C50	2	86	172	86
EP2C70	3	150	300	150

Note to Table 2–11:

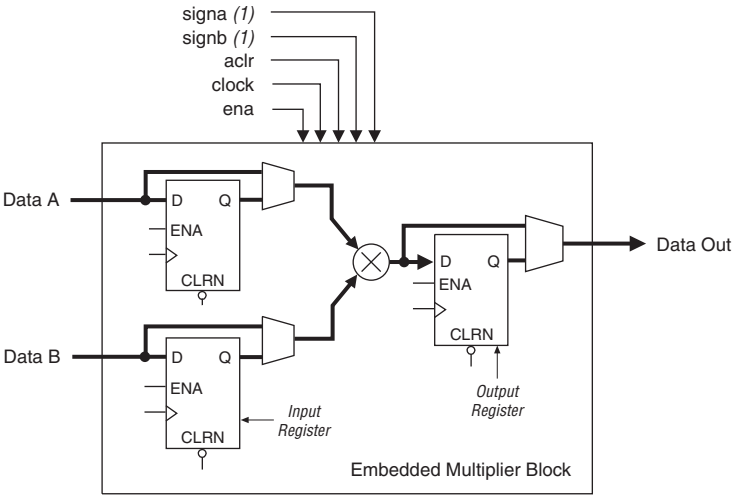
(1) Each device has either the number of 9 × 9-, or 18 × 18-bit multipliers shown. The total number of multipliers for each device is not the sum of all the multipliers.

The embedded multiplier consists of the following elements:

- Multiplier block
- Input and output registers
- Input and output interfaces

Figure 2–18 shows the multiplier block architecture.

Figure 2–18. Multiplier Block Architecture



Note to Figure 2–18:
(1) If necessary, these signals can be registered once to match the data signal path.

Each multiplier operand can be a unique signed or unsigned number. Two signals, `signa` and `signb`, control the representation of each operand respectively. A logic 1 value on the `signa` signal indicates that data A is a signed number while a logic 0 value indicates an unsigned number. Table 2–12 shows the sign of the multiplication result for the various operand sign representations. The result of the multiplication is signed if any one of the operands is a signed value.

Table 2–12. Multiplier Sign Representation

Data A (signa Value)	Data B (signb Value)	Result
Unsigned	Unsigned	Unsigned
Unsigned	Signed	Signed
Signed	Unsigned	Signed
Signed	Signed	Signed

There is only one signa and one signb signal for each dedicated multiplier. Therefore, all of the data A inputs feeding the same dedicated multiplier must have the same sign representation. Similarly, all of the data B inputs feeding the same dedicated multiplier must have the same sign representation. The signa and signb signals can be changed dynamically to modify the sign representation of the input operands at run time. The multiplier offers full precision regardless of the sign representation and can be registered using dedicated registers located at the input register stage.

Multiplier Modes

Table 2–13 summarizes the different modes that the embedded multipliers can operate in.

Table 2–13. Embedded Multiplier Modes

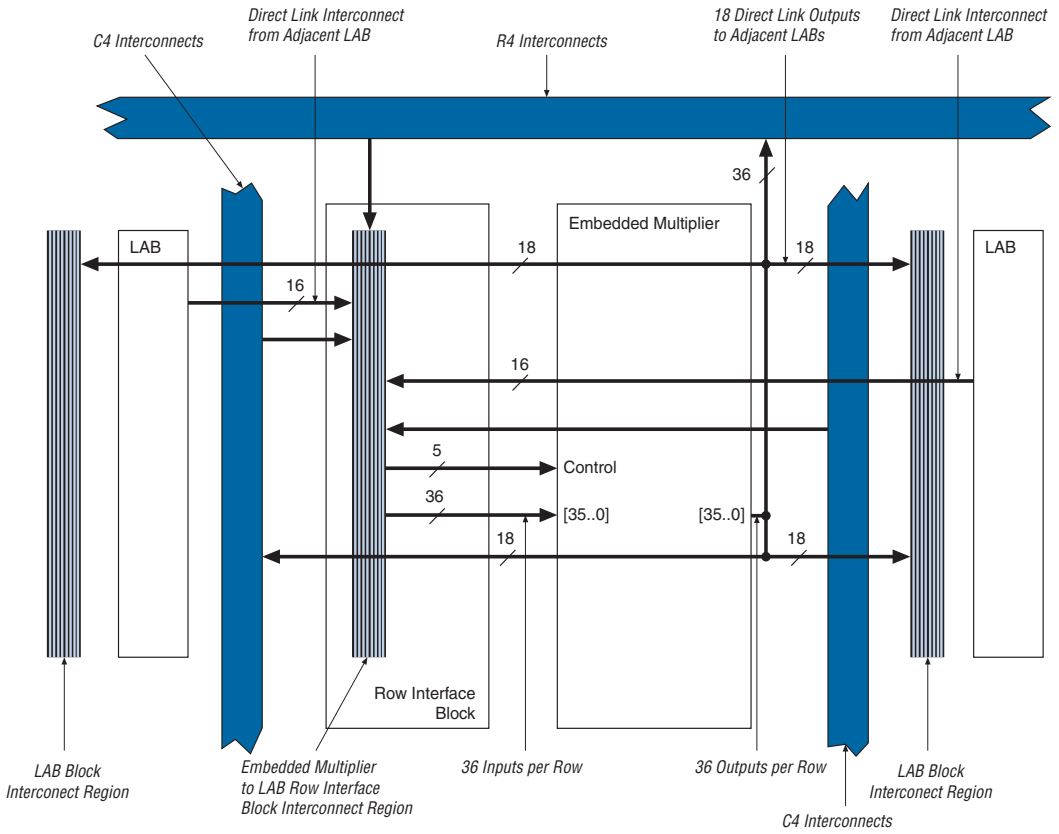
Multiplier Mode	Description
18-bit Multiplier	An embedded multiplier can be configured to support a single 18 × 18 multiplier for operand widths up to 18 bits. All 18-bit multiplier inputs and results can be registered independently. The multiplier operands can accept signed integers, unsigned integers, or a combination of both.
9-bit Multiplier	An embedded multiplier can be configured to support two 9 × 9 independent multipliers for operand widths up to 9-bits. Both 9-bit multiplier inputs and results can be registered independently. The multiplier operands can accept signed integers, unsigned integers or a combination of both. There is only one signa signal to control the sign representation of both data A inputs and one signb signal to control the sign representation of both data B inputs of the 9-bit multipliers within the same dedicated multiplier.

Embedded Multiplier Routing Interface

The R4, C4, and direct link interconnects from adjacent LABs drive the embedded multiplier row interface interconnect. The embedded multipliers can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 16 direct link input connections to the embedded multiplier are possible from the left adjacent LABs and another 16 possible from the right adjacent LAB. Embedded multiplier

outputs can also connect to left and right LABs through 18 direct link interconnects each. Figure 2–19 shows the embedded multiplier to logic array interface.

Figure 2–19. Embedded Multiplier LAB Row Interface



There are five dynamic control input signals that feed the embedded multiplier: `signa`, `signb`, `clk`, `clkena`, and `aclr`. `signa` and `signb` can be registered to match the data signal input path. The same `clk`, `clkena`, and `aclr` signals feed all registers within a single embedded multiplier.

For more information on Cyclone II embedded multipliers, see the *Embedded Multipliers in Cyclone II Devices* chapter.

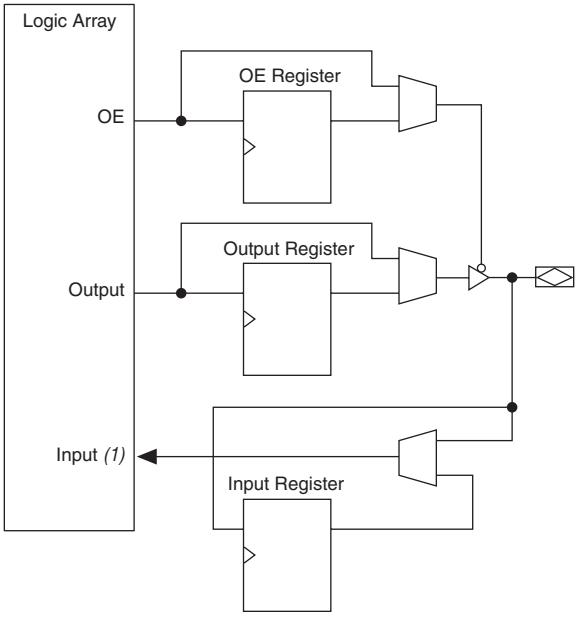
I/O Structure & Features

IOEs support many features, including:

- Differential and single-ended I/O standards
- 3.3-V, 64- and 32-bit, 66- and 33-MHz PCI compliance
- Joint Test Action Group (JTAG) boundary-scan test (BST) support
- Output drive strength control
- Weak pull-up resistors during configuration
- Tri-state buffers
- Bus-hold circuitry
- Programmable pull-up resistors in user mode
- Programmable input and output delays
- Open-drain outputs
- DQ and DQS I/O pins
- V_{REF} pins

Cyclone II device IOEs contain a bidirectional I/O buffer and three registers for complete embedded bidirectional single data rate transfer. Figure 2–20 shows the Cyclone II IOE structure. The IOE contains one input register, one output register, and one output enable register. The designer can use the input registers for fast setup times and output registers for fast clock-to-output times. Additionally, the designer can use the output enable (OE) register for fast clock-to-output enable timing. The Quartus II software automatically duplicates a single OE register that controls multiple output or bidirectional pins. Designers can use IOEs as input, output, or bidirectional pins.

Figure 2–20. Cyclone II IOE Structure

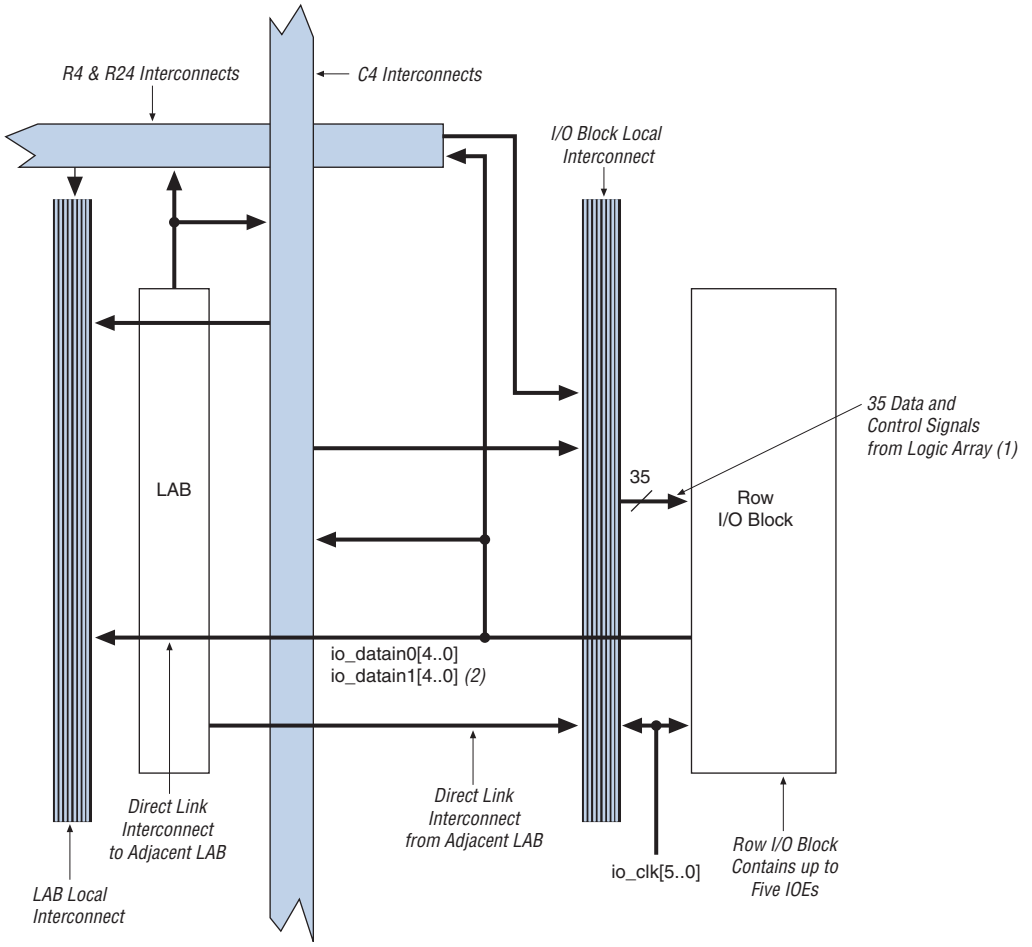


Note to Figure 2–20:

(1) There are two paths available for combinatorial or registered inputs to the logic array. Each path contains a unique programmable delay chain.

The IOEs are located in I/O blocks around the periphery of the Cyclone II device. There are up to five IOEs per row I/O block and up to four IOEs per column I/O block (column I/O blocks span two columns). The row I/O blocks drive row, column (only C4 interconnects), or direct link interconnects. The column I/O blocks drive column interconnects. Figure 2–21 shows how a row I/O block connects to the logic array. Figure 2–22 shows how a column I/O block connects to the logic array.

Figure 2–21. Row I/O Block Connection to the Interconnect

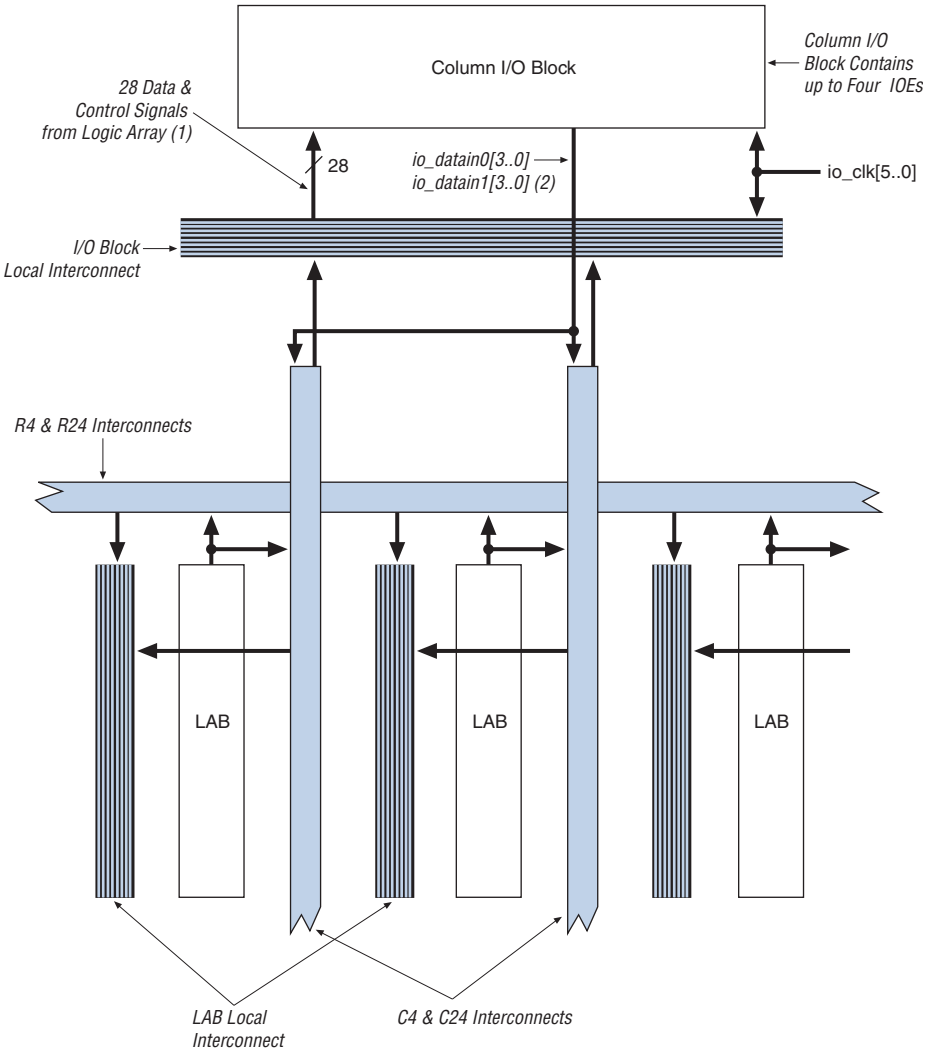


Notes to Figure 2–21:

(1) The 35 data and control signals consist of five data out lines, `io_dataout[4..0]`, five output enables, `io_coe[4..0]`, five input clock enables, `io_cce_in[4..0]`, five output clock enables, `io_cce_out[4..0]`, five clocks, `io_cclk[4..0]`, five asynchronous clear signals, `io_caclr[4..0]`, and five synchronous clear signals, `io_csclr[4..0]`.

(2) Each of the five IOEs in the row I/O block can have two `io_datain` input (combinatorial or registered) inputs.

Figure 2–22. Column I/O Block Connection to the Interconnect



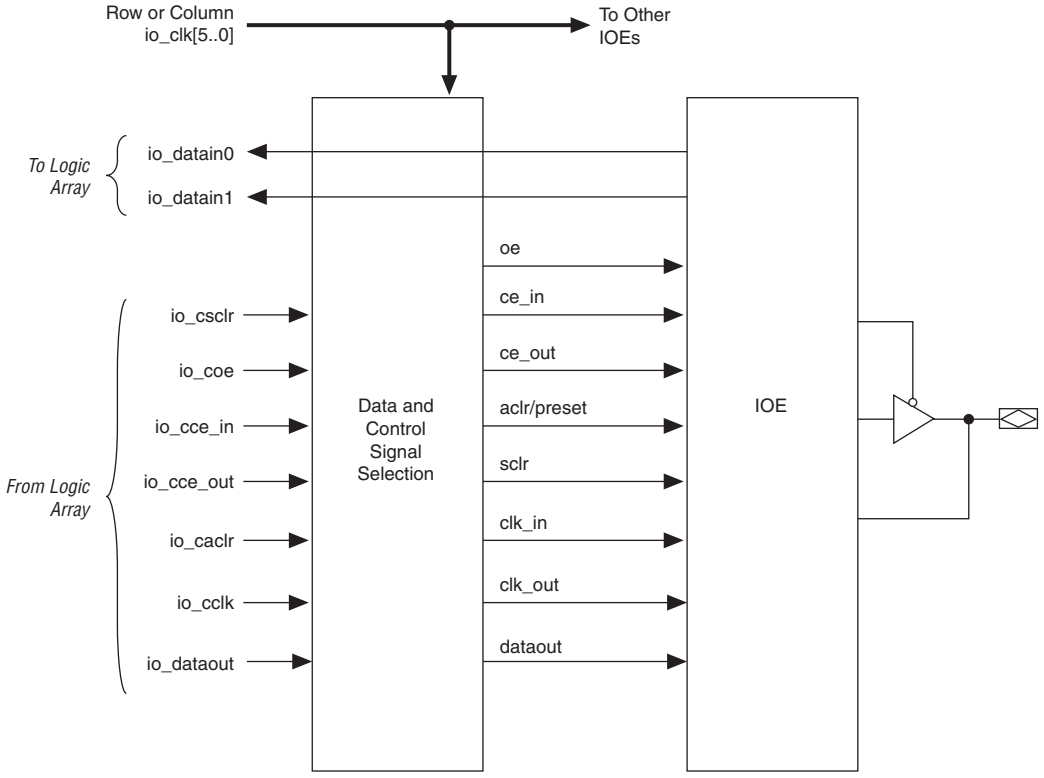
Notes to Figure 2–22:

(1) The 28 data and control signals consist of four data out lines, `io_dataout[3..0]`, four output enables, `io_coe[3..0]`, four input clock enables, `io_cce_in[3..0]`, four output clock enables, `io_cce_out[3..0]`, four clocks, `io_cclk[3..0]`, four asynchronous clear signals, `io_caclr[3..0]`, and four synchronous clear signals, `io_csclr[3..0]`.

(2) Each of the four IOEs in the column I/O block can have two `io_datain` input (combinatorial or registered) inputs.

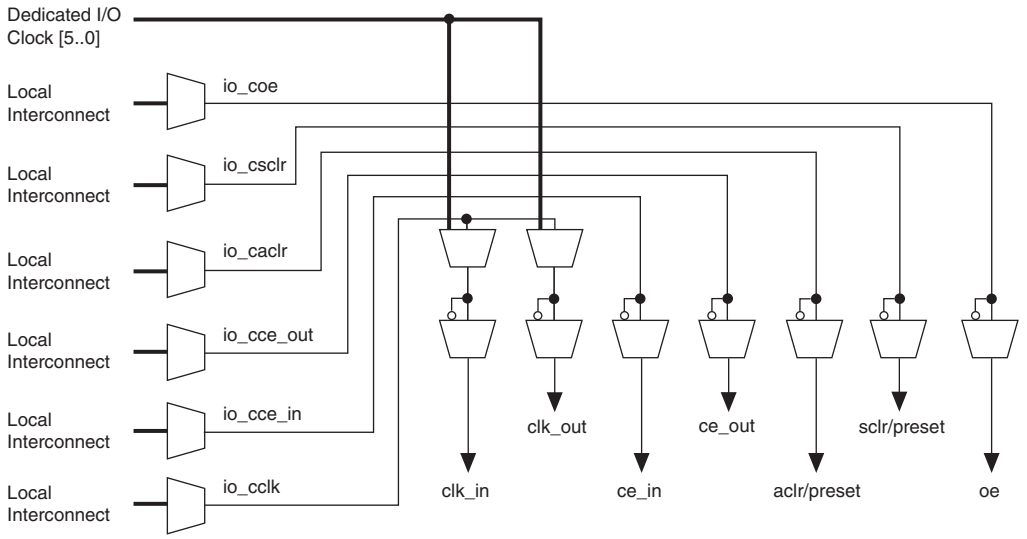
The pin's datain signals can drive the logic array. The logic array drives the control and data signals, providing a flexible routing resource. The row or column IOE clocks, io_clk[5..0], provide a dedicated routing resource for low-skew, high-speed clocks. The global clock network generates the IOE clocks that feed the row or column I/O regions (see "Global Clock Network & Phase-Locked Loops" on page 2–16). Figure 2–23 illustrates the signal paths through the I/O block.

Figure 2–23. Signal Path through the I/O Block



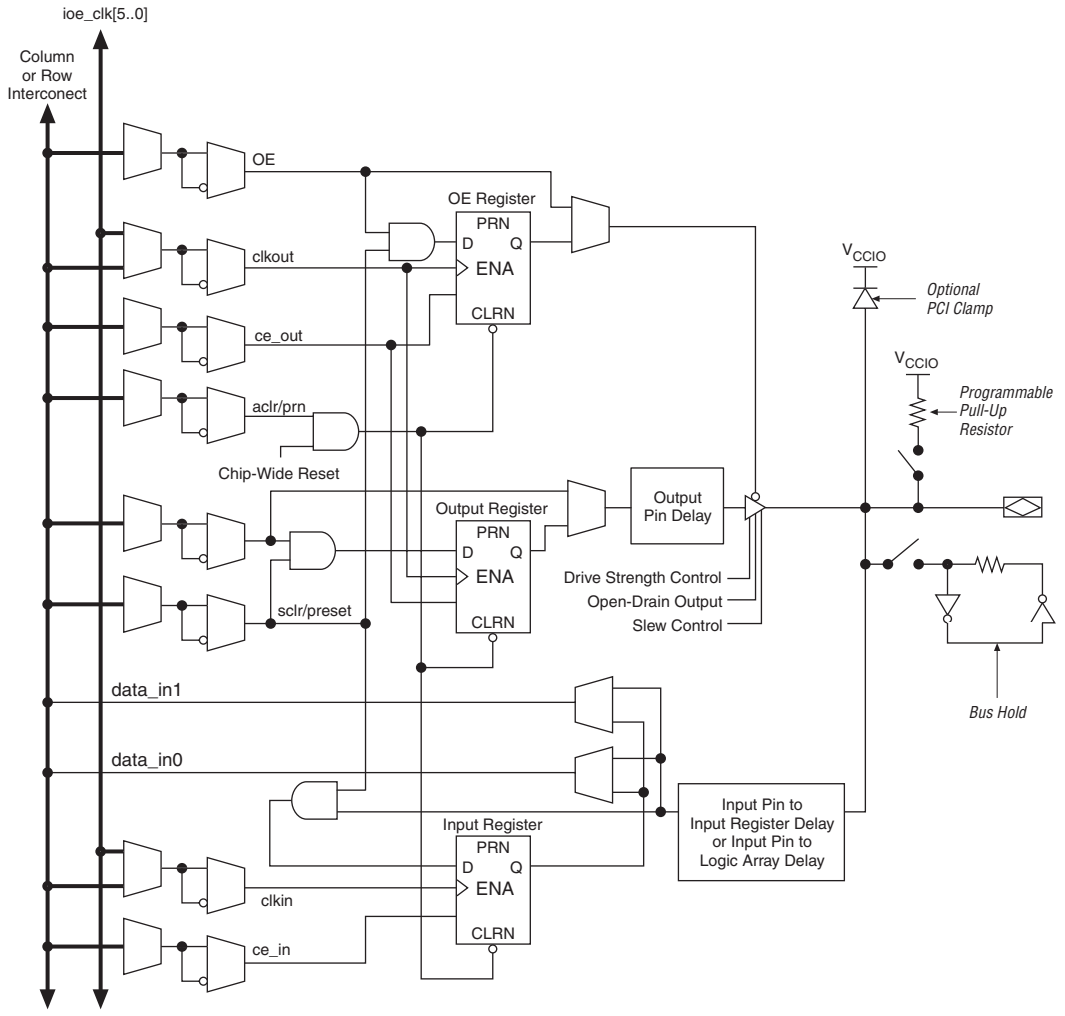
Each IOE contains its own control signal selection for the following control signals: oe, ce_in, ce_out, aclr/preset, sclr/preset, clk_in, and clk_out. Figure 2–24 illustrates the control signal selection.

Figure 2–24. Control Signal Selection per IOE



In normal bidirectional operation, the designer can use the input register for input data requiring fast setup times. The input register can have its own clock input and clock enable separate from the OE and output registers. The designer can use the output register for data requiring fast clock-to-output performance. The OE register is available for fast clock-to-output enable timing. The OE and output register share the same clock source and the same clock enable source from the local interconnect in the associated LAB, dedicated I/O clocks, or the column and row interconnects. All registers share sclr and aclr, but each register can individually disable sclr and aclr. Figure 2–25 shows the IOE in bidirectional configuration.

Figure 2–25. Cyclone II IOE in Bidirectional I/O Configuration



The Cyclone II device IOE includes programmable delays to ensure zero hold times, minimize setup times, or increase clock to output times.

A path in which a pin directly drives a register may require a programmable delay to ensure zero hold time, whereas a path in which a pin drives a register through combinatorial logic may not require the delay. Programmable delays decrease input-pin-to-logic-array and IOE input register delays. The Quartus II Compiler can program these delays to automatically minimize setup time while providing a zero hold time.

Programmable delays can increase the register-to-pin delays for output registers. Table 2–14 shows the programmable delays for Cyclone II devices.

Table 2–14. Cyclone II Programmable Delay Chain

Programmable Delays	Quartus II Logic Option
Input pin to logic array delay	Input delay from pin to internal cells
Input pin to input register delay	Input delay from pin to input register
Output pin delay	Delay from output register to output pin

There are two paths in the IOE for an input to reach the logic array. Each of the two paths can have a different delay. This allows the designer to adjust delays from the pin to internal LE registers that reside in two different areas of the device. The designer sets the two combinatorial input delays by selecting different delays for two different paths under the **Input delay from pin to internal cells logic** option in the Quartus II software. However, if the pin uses the input register, one of delays will be disregarded since the IOE only has two paths to internal logic. If the input register is used, the IOE uses one input path. The other input path is then available for the combinatorial path, and only one input delay assignment is applied.

The IOE registers in each I/O block share the same source for clear or preset. The designer can program preset or clear for each individual IOE, but both features cannot be used simultaneously. The designer can also program the registers to power up high or low after configuration is complete. If programmed to power up low, an asynchronous clear can control the registers. If programmed to power up high, an asynchronous preset can control the registers. This feature prevents the inadvertent activation of another device's active-low input upon power up. If one register in an IOE uses a preset or clear signal then all registers in the IOE must use that same signal if they require preset or clear. Additionally a synchronous reset signal is available to the designer for the IOE registers.

External Memory Interfacing

Cyclone II devices support a broad range of external memory interfaces such as SDR SDRAM, DDR SDRAM, DDR2 SDRAM, and QDRII SRAM external memories. Cyclone II devices feature dedicated high-speed interfaces that transfer data between external memory devices at up to 167 MHz/333 Mbps for DDR and DDR2 SDRAM devices and 167 MHz/667 Mbps for QDRII SRAM devices. The programmable DQS delay chain allows designers to fine tune the phase shift for the input clocks or strobes to properly align clock edges as needed to capture data.

In Cyclone II devices, all the I/O banks support SDR and DDR SDRAM memory up to 167 MHz/333 Mbps. All I/O banks support DQS signals with the DQ bus modes of ×8/×9, or ×16/×18. Table 2–15 shows the external memory interfaces supported in Cyclone II devices.

Table 2–15. External Memory Support in Cyclone II Devices *Note (1)*

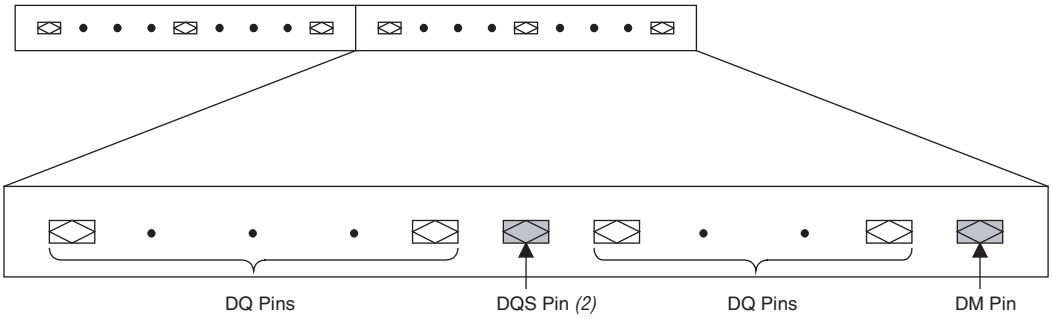
Memory Standard	I/O Standard	Maximum Bus Width	Maximum Clock Rate Supported (MHz)	Maximum Data Rate Supported (Mbps)
SDR SDRAM	LVTTL *(2)*	72	167	167
DDR SDRAM	SSTL-2 class I *(2)*	72	167	333 *(1)*
	SSTL-2 class II *(2)*	72	133	267 *(1)*
DDR2 SDRAM	SSTL-18 class I *(2)*	72	167	333 *(1)*
	SSTL-18 class II *(3)*	72	125	250 *(1)*
QDRII SRAM *(4)*	1.8-V HSTL class I *(2)*	36	167	668 *(1)*
	1.8-V HSTL class II *(3)*	36	100	400 *(1)*

Notes to Table 2–15:

(1) The data rate is for designs using the Clock Delay Control circuitry.
(2) The I/O standards are supported on all the I/O banks of the Cyclone II device.
(3) The I/O standards are supported only on the I/O banks on the top and bottom of the Cyclone II device.
(4) For maximum performance, Altera recommends using the 1.8-V HSTL I/O standard because of higher I/O drive strength. QDRII SRAM devices also support the 1.5-V HSTL I/O standard.

Cyclone II devices use data (DQ), data strobe (DQS), and clock pins to interface with external memory. Figure 2–26 shows the DQ and DQS pins in the ×8/×9 mode.

Figure 2–26. Cyclone II Device DQ & DQS Groups in ×8/×9 Mode *Notes (1), (2)*



Notes to Figure 2–26:
(1) Each DQ group consists of a DQS pin, DM pin, and up to nine DQ pins.
(2) This is an idealized pin layout. For actual pin layout, refer to the pin table.

Cyclone II devices support the data strobe or read clock signal (DQS) used in DDR and DDR2 SDRAM. Cyclone II devices can use either bidirectional data strobes or unidirectional read clocks. The dedicated external memory interface in Cyclone II devices also includes programmable delay circuitry that can shift the incoming DQS signals to center align the DQS signals within the data window.

The DQS signal is usually associated with a group of data (DQ) pins. The phase-shifted DQS signals drive the global clock network, which is used to clock the DQ signals on internal LE registers.

Table 2–16 shows the number of DQ pin groups per device.

Table 2–16. Cyclone II DQS & DQ Bus Mode Support (Part 1 of 2) *Note (1)*

Device	Package	Number of ×8 Groups	Number of ×9 Groups	Number of ×16 Groups	Number of ×18 Groups
EP2C5	144-pin TQFP *(2)*	3	3	0	0
	208-pin PQFP *(2)*	7	4	3	3
EP2C8	144-pin TQFP	3	3	0	0
	208-pin PQFP	7	4	3	3
	256-pin FineLine BGA	8	4	4	4
EP2C20	256-pin FineLine BGA	8	4	4	4
	484-pin FineLine BGA	16	8	8	8
EP2C35	484-pin FineLine BGA	16	8	8	8
	672-pin FineLine BGA	16	8	8	8

Table 2–16. Cyclone II DQS & DQ Bus Mode Support (Part 2 of 2) *Note (1)*

Device	Package	Number of ×8 Groups	Number of ×9 Groups	Number of ×16 Groups	Number of ×18 Groups
EP2C50	484-pin FineLine BGA	16	8	8	8
	672-pin FineLine BGA	16	8	8	8
EP2C70	672-pin FineLine BGA	16	8	8	8
	896-pin FineLine BGA	16	8	8	8

Notes to Table 2–16:
(1) Numbers are preliminary until the devices are available.
(2) EP2C5 and EP2C8 devices in the 144-pin TQFP package do not have any DQ pin groups in I/O bank 1.

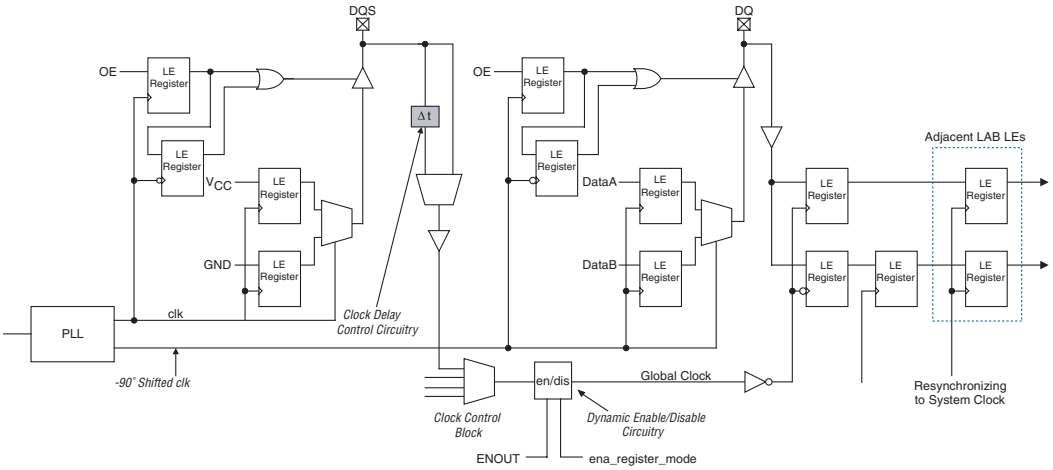
Designers can use any of the DQ pins for the parity pins in Cyclone II devices. The Cyclone II device family supports parity in the ×8/×9, and ×16/×18 mode. There is one parity bit available per eight bits of data pins.

The data mask, DM, pins are required when writing to DDR SDRAM and DDR2 SDRAM devices. A low signal on the DM pin indicates that the write is valid. If the DM signal is high, the memory masks the DQ signals. In Cyclone II devices, the DM pins are assigned and are the preferred pins. Each group of DQS and DQ signals requires a DM pin.

When using the Cyclone II I/O banks to interface with the DDR memory, at least one PLL with two clock outputs is needed to generate the system and write clock. The system clock is used to clock the DQS write signals, commands, and addresses. The write clock is shifted by –90° from the system clock and is used to clock the DQ signals during writes.

Figure 2–27 illustrates DDR SDRAM interfacing from the I/O through the dedicated circuitry to the logic array.

Figure 2–27. DDR SDRAM Interfacing



For more information on Cyclone II external memory interfaces, see the *External Memory Interfaces* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Programmable Drive Strength

The output buffer for each Cyclone II device I/O pin has a programmable drive strength control for certain I/O standards. The LVTTL, LVCMOS, SSTL-2 class I and II, SSTL-18 class I and II, HSTL-18 class I and II, and HSTL-1.5 class I and II standards have several levels of drive strength that the designer can control. Using minimum settings provides signal slew rate control to reduce system noise and signal overshoot. Table 2–17 shows the possible settings for the I/O standards with drive strength control.

Table 2–17. Programmable Drive Strength (Part 1 of 2)

I/O Standard	I_{OH}/I_{OL} Current Strength Setting (mA)	
	Top & Bottom I/O Pins	Side I/O Pins
LVTTL (3.3 V)	4	4
	8	8
	12	12
	16	16
	20	20
	24	24
LVCMOS (3.3 V)	4	4
	8	8
	12	12
	16	
	20	
	24	
LVTTL/LVCMOS (2.5 V)	4	4
	8	8
	12	
	16	
LVTTL/LVCMOS (1.8 V)	2	2
	4	4
	6	6
	8	8
	10	10
	12	12

Table 2–17. Programmable Drive Strength (Part 2 of 2)

I/O Standard	I_{OH}/I_{OL} Current Strength Setting (mA)	
	Top & Bottom I/O Pins	Side I/O Pins
LVCMOS (1.5 V)	2	2
	4	4
	6	6
	8	
SSTL-2 class I	8	8
	12	12
SSTL-2 class II	16	16
	20	
	24	
SSTL-18 class I	4	4
	6	6
	8	8
	10	10
	12	
SSTL-18 class II	8	
	16	
	18	
HSTL-18 class I	4	4
	6	6
	8	8
	10	10
	12	12
HSTL-18 class II	16	
	18	
	20	
HSTL-15 class I	4	4
	6	6
	8	8
	10	
	12	
HSTL-15 class II	16	

Open-Drain Output

Cyclone II devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (that is, interrupt and write-enable signals) that can be asserted by any of several devices.

Slew Rate Control

Slew rate control is performed by using programmable output drive strength.

Bus Hold

Each Cyclone II device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry can hold the signal on an I/O pin at its last-driven state. Since the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage where noise can cause unintended high-frequency switching. The designer can select this feature individually for each I/O pin. The bus-hold output will drive no higher than V_{CCIO} to prevent overdriving signals.

If the bus-hold feature is enabled, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus hold circuitry is not available on the dedicated clock pins.

The bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

The bus-hold circuitry uses a resistor with a nominal resistance (R_{BH}) of approximately 7 kΩ to pull the signal level to the last-driven state. Refer to the *DC Characteristics & Timing Specifications* chapter in Volume 1 of the *Cyclone II Device Handbook* for the specific sustaining current for each V_{CCIO} voltage level driven through the resistor and overdrive current used to identify the next driven input level.

Programmable Pull-Up Resistor

Each Cyclone II device I/O pin provides an optional programmable pull-up resistor during user mode. If the designer enables this feature for an I/O pin, the pull-up resistor (typically 25 kΩ) holds the output to the V_{CCIO} level of the output pin's bank.

If the programmable pull-up is enabled, the device cannot use the bus-hold feature. The programmable pull-up resistors are not supported on the dedicated configuration, JTAG, and dedicated clock pins.

Advanced I/O Standard Support

Table 2–18 shows the I/O standards supported by Cyclone II devices and which I/O pins support them.

Table 2–18. Cyclone II Supported I/O Standards & Constraints (Part 1 of 2)

I/O Standard	Type	V_{CCIO} Level		Top & Bottom I/O Pins		Side I/O Pins		
		Input	Output	CLK, DQS	User I/O Pins	CLK, DQS	PLL_OUT	User I/O Pins
3.3-V LVTTL and LVCMOS	Single ended	3.3 V/ 2.5 V	3.3 V	✓	✓	✓	✓	✓
2.5-V LVTTL and LVCMOS	Single ended	3.3 V/ 2.5 V	2.5 V	✓	✓	✓	✓	✓
1.8-V LVTTL and LVCMOS	Single ended	1.8 V/ 1.5 V	1.8 V	✓	✓	✓	✓	✓
1.5-V LVCMOS	Single ended	1.8 V/ 1.5 V	1.5 V	✓	✓	✓	✓	✓
SSTL-2 class I	Voltage referenced	2.5 V	2.5 V	✓	✓	✓	✓	✓
SSTL-2 class II	Voltage referenced	2.5 V	2.5 V	✓	✓	✓	✓	✓
SSTL-18 class I	Voltage referenced	1.8 V	1.8 V	✓	✓	✓	✓	✓
SSTL-18 class II	Voltage referenced	1.8 V	1.8 V	✓	✓	*(1)*	*(1)*	*(1)*
HSTL-18 class I	Voltage referenced	1.8 V	1.8 V	✓	✓	✓	✓	✓
HSTL-18 class II	Voltage referenced	1.8 V	1.8 V	✓	✓	*(1)*	*(1)*	*(1)*

Table 2–18. Cyclone II Supported I/O Standards & Constraints (Part 2 of 2)

I/O Standard	Type	V_{CCIO} Level		Top & Bottom I/O Pins		Side I/O Pins		
		Input	Output	CLK, DQS	User I/O Pins	CLK, DQS	PLL_OUT	User I/O Pins
HSTL-15 class I	Voltage referenced	1.5 V	1.5 V	✓	✓	✓	✓	✓
HSTL-15 class II	Voltage referenced	1.5 V	1.5 V	✓	✓	*(1)*	*(1)*	*(1)*
PCI and PCI-X *(2)*	Single ended	3.3 V	3.3 V			✓	✓	✓
Differential SSTL-2 class I or class II	Pseudo differential *(3)*	*(4)*	2.5 V				✓	
		2.5 V	*(4)*	✓ *(5)*		✓ *(5)*		
Differential SSTL-18 class I or class II	Pseudo differential *(3)*	*(4)*	1.8 V				✓ *(6)*	
		1.8 V	*(4)*	✓ *(5)*		✓ *(5)*		
Differential HSTL-15 class I or class II	Pseudo differential *(3)*	*(4)*	1.5 V				✓ *(6)*	
		1.5 V	*(4)*	✓ *(5)*		✓ *(5)*		
Differential HSTL-18 class I or class II	Pseudo differential *(3)*	*(4)*	1.8 V				✓ *(6)*	
		1.8 V	*(4)*	✓ *(5)*		✓ *(5)*		
LVDS	Differential	2.5 V	2.5 V	✓	✓	✓	✓	✓
RSDS and mini-LVDS *(7)*	Differential	*(4)*	2.5 V		✓		✓	✓
LVPECL *(8)*	Differential	3.3 V/ 2.5 V/ 1.8 V/ 1.5 V	*(4)*	✓		✓		

Notes to Table 2–18:

(1) These pins support SSTL-18 class II and 1.8- and 1.5-V HSTL class II inputs.
(2) PCI-X does not meet the IV curve requirement at the linear region. PCI-clamp diode is not available on top and bottom I/O pins.
(3) Pseudo-differential HSTL and SSTL outputs use two single-ended outputs with the second output programmed as inverted. Pseudo-differential HSTL and SSTL inputs treat differential inputs as two single-ended HSTL and SSTL inputs and only decode one of them.
(4) This I/O standard is not supported on these I/O pins.
(5) This I/O standard is only supported on the dedicated clock pins.
(6) PLL_OUT does not support differential SSTL-18 class II and differential 1.8 and 1.5-V HSTL class II.
(7) mini-LVDS and RSDS are only supported on output pins.
(8) LVPECL is only supported on clock inputs.

For more information on Cyclone II supported I/O standards, see the *Selectable I/O Standards in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

High-Speed Differential Interfaces

Cyclone II devices can transmit and receive data through LVDS signals at a data rate of up to 622 Mbps and 805 Mbps, respectively. For the LVDS transmitter and receiver, the Cyclone II device's input and output pins support serialization and deserialization through internal logic.

The reduced swing differential signaling (RSDS) and mini-LVDS standards are derivatives of the LVDS standard. The RSDS and mini-LVDS I/O standards are similar in electrical characteristics to LVDS, but have a smaller voltage swing and therefore provide increased power benefits and reduced electromagnetic interference (EMI). Cyclone II devices support the RSDS and mini-LVDS I/O standards at data rates up to 170 Mbps at the transmitter. For RSDS and mini-LVDS, the maximum internal clock frequency is 85 MHz.

A subset of pins in each I/O bank (on both rows and columns) support the high-speed I/O interface. The dual-purpose LVDS pins require an external-resistor network at the transmitter channels in addition to 100-Ω termination resistors on receiver channels. These pins do not contain dedicated serialization or deserialization circuitry. Therefore, internal logic performs serialization and deserialization functions.

Cyclone II pin tables list the pins that support the high-speed I/O interface. The number of LVDS channels supported in each device family member is listed in Table 2–19.

Table 2–19. Cyclone II Device LVDS Channels (Part 1 of 2)

Device	Pin Count	Number of LVDS Channels *(1)*
EP2C5	144	33 (35)
	208	58 (60)
EP2C8	144	31 (33)
	208	55 (57)
	256	77 (79)
EP2C20	256	56 (60)
	484	132 (136)
EP2C35	484	135(139)
	672	205 (209)

Table 2–19. Cyclone II Device LVDS Channels (Part 2 of 2)

Device	Pin Count	Number of LVDS Channels *(1)*
EP2C50	484	122 (126)
	672	193 (197)
EP2C70	672	164 (168)
	896	261 (265)

Note to Table 2–19:

(1) The first number represents the number of bidirectional I/O pins which can be used as inputs or outputs. The number in parenthesis includes dedicated clock input pin pairs which can only be used as inputs.

You can use I/O pins and internal logic to implement a high-speed I/O receiver and transmitter in Cyclone II devices. Cyclone II devices do not contain dedicated serialization or deserialization circuitry. Therefore, shift registers, internal PLLs, and IOEs are used to perform serial-to-parallel conversions on incoming data and parallel-to-serial conversion on outgoing data.

The maximum internal clock frequency for a receiver is 402.5 MHz. The maximum internal clock frequency for a transmitter is 311 MHz. The maximum data rate of 805 Mbps is only achieved when DDIO registers are used. The LVDS standard does not require an input reference voltage, but it does require a 100-Ω termination resistor between the two signals at the input buffer. An external resistor network is required on the transmitter side.

For more information on Cyclone II differential I/O interfaces, see the *High-Speed Differential Interfaces in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Series On-Chip Termination

On-chip termination helps to prevent reflections and maintain signal integrity. This also minimizes the need for external resistors in high pin count ball grid array (BGA) packages. Cyclone II devices provide I/O driver on-chip impedance matching and on-chip series termination for single-ended outputs and bidirectional pins.

Cyclone II devices support driver impedance matching to the impedance of the transmission line, typically 25 or 50 Ω. When used with the output drivers, on-chip termination sets the output driver impedance to 25 or 50 Ω. Cyclone II devices also support I/O driver series termination (R_S = 50 Ω) for SSTL-2 and SSTL-18. Table 2–20 lists the I/O standards that support impedance matching and series termination.

Table 2–20. I/O Standards Supporting Series Termination *Note (1)*

I/O Standards	Target R_S (Ω)	V_{CCIO} (V)
3.3-V LVTTL and LVCMOS	25 *(2)*	3.3
2.5-V LVTTL and LVCMOS	50 *(2)*	2.5
1.8-V LVTTL and LVCMOS	50 *(2)*	1.8
SSTL-2 class I	50 *(2)*	2.5
SSTL-18 class I	50 *(2)*	1.8

Notes to Table 2–20:

(1) Supported conditions are junction temperature (T_J) = 0° to 85° C and V_{CCIO} = V_{CCIO} ±50 mV.

(2) These R_S values are nominal values. Actual impedance will vary across process, voltage, and temperature conditions. Tolerance is pending characterization.

The recommended frequency range of operation is pending silicon characterization.

On-chip series termination can be supported on any I/O bank. V_{CCIO} and V_{REF} must be compatible for all I/O pins in order to enable on-chip series termination in a given I/O bank. I/O standards that support different R_S values can reside in the same I/O bank as long as their V_{CCIO} and V_{REF} are not conflicting.

When using on-chip series termination, programmable drive strength is not available.

Impedance matching is implemented using the capabilities of the output driver and is subject to a certain degree of variation, depending on the process, voltage and temperature. The actual tolerance is pending silicon characterization.

I/O Banks

The I/O pins on Cyclone II devices are grouped together into I/O banks and each bank has a separate power bus. EP2C5 and EP2C8 devices have four I/O banks (see Figure 2–28), while EP2C20, EP2C35, EP2C50, and EP2C70 devices have eight I/O banks (see Figure 2–29). Each device I/O pin is associated with one I/O bank. To accommodate voltage-referenced I/O standards, each Cyclone II I/O bank has a VREF bus. Each bank in EP2C5, EP2C8, EP2C20, EP2C35, and EP2C50 devices supports two VREF pins and each bank of EP2C70 supports three VREF pins. When using the VREF pins, each VREF pin must be properly connected to the appropriate voltage level. In the event these pins are not used as VREF pins, they may be used as regular I/O pins.

The top and bottom I/O banks (banks 2 and 4 in EP2C5 and EP2C8 devices and banks 3, 4, 7, and 8 in EP2C20, EP2C35, EP2C50, and EP2C70 devices) support all I/O standards listed in Table 2–18, except the PCI/PCI-X I/O standards. The left and right side I/O banks (banks 1 and 3 in EP2C5 and EP2C8 devices and banks 1, 2, 5, and 6 in EP2C20, EP2C35, EP2C50, and EP2C70 devices) support I/O standards listed in Table 2–18, except SSTL-18 class II, HSTL-18 class II, and HSTL-15 class II I/O standards. See Table 2–18 for a complete list of supported I/O standards.

The top and bottom I/O banks (banks 2 and 4 in EP2C5 and EP2C8 devices and banks 3, 4, 7, and 8 in EP2C20, EP2C35, EP2C50, and EP2C70 devices) support DDR2 memory up to 167 MHz/333 Mbps and QDR memory up to 167 MHz/668 Mbps. The left and right side I/O banks (1 and 3 of EP2C5 and EP2C8 devices and 1, 2, 5, and 6 of EP2C20, EP2C35, EP2C50, and EP2C70 devices) only support SDR and DDR SDRAM interfaces. All the I/O banks of the Cyclone II devices support SDR memory up to 167 MHz/167 Mbps and DDR memory up to 167 MHz/333 Mbps.

Figure 2–28. EP2C5 & EP2C8 I/O Banks *Notes (1), (2)*

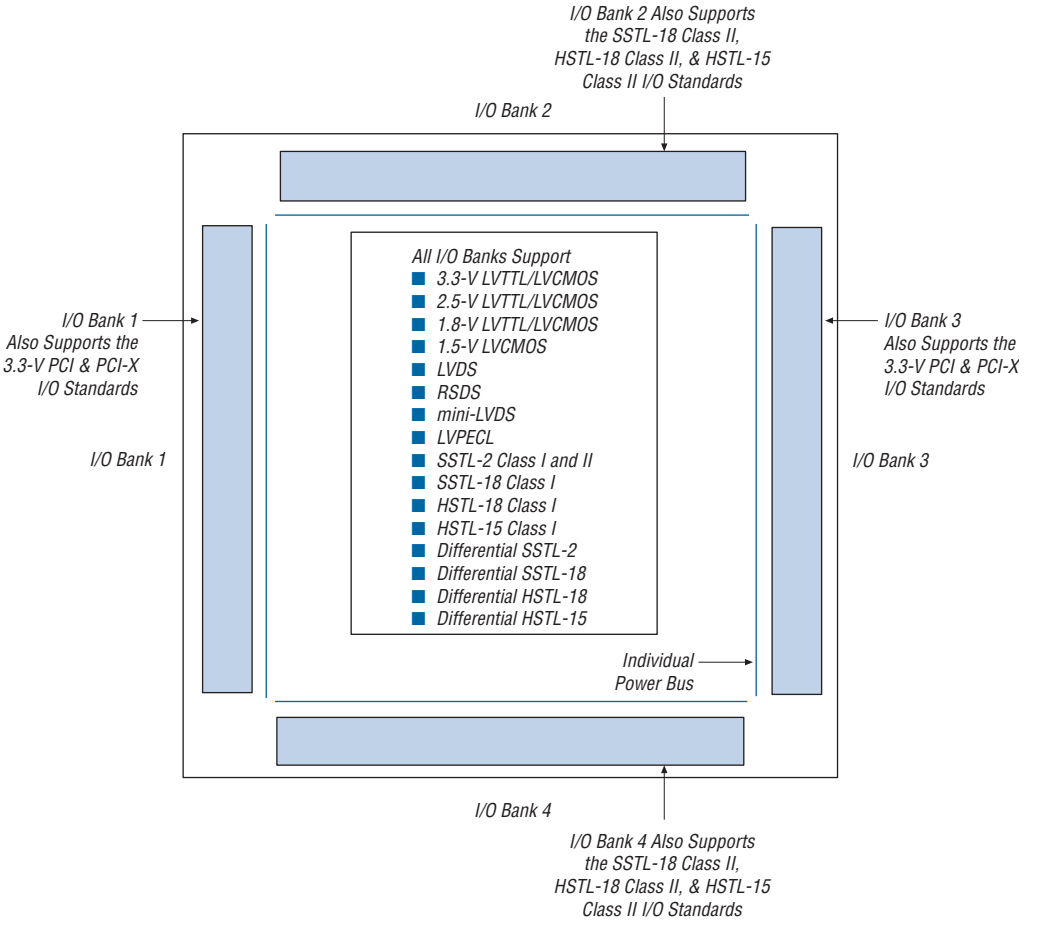
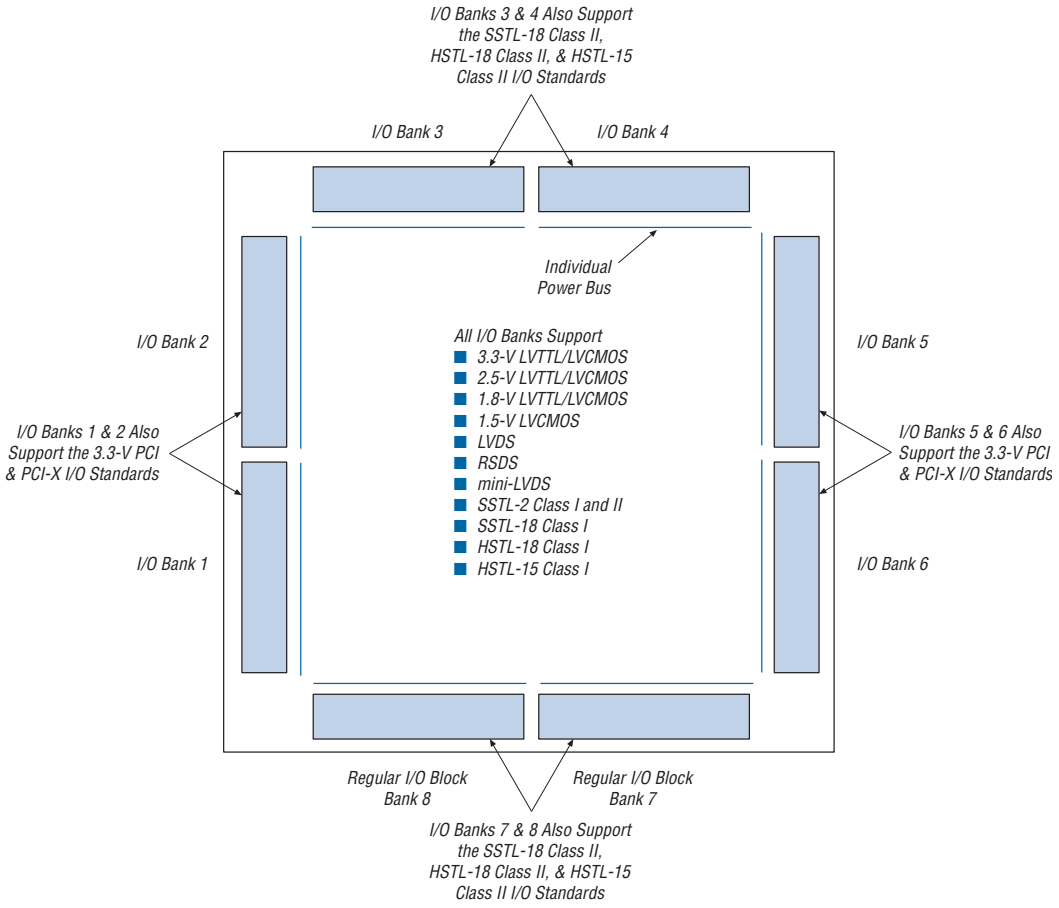


Figure 2–29. EP2C20, EP2C35, EP2C50 & EP2C70 I/O Banks *Notes (1), (2)*



Notes to Figure 2–28 & 2–29:
(1) This is a top view of the silicon die.
(2) This is a graphic representation only. Refer to the pin list and the Quartus II software for exact pin locations.

Each I/O bank has its own VCCIO pins. A single device can support 1.5-V, 1.8-V, 2.5-V, and 3.3-V interfaces; each individual bank can support a different standard with different I/O voltages. Each bank also has dual-purpose VREF pins to support any one of the voltage-referenced standards (e.g., SSTL-2) independently. If an I/O bank does not use voltage-referenced standards, the VREF pins are available as user I/O pins.

Each I/O bank can support multiple standards with the same V_{CCIO} for input and output pins. For example, when V_{CCIO} is 3.3-V, a bank can support LVTTL, LVCMOS, and 3.3-V PCI for inputs and outputs. Voltage-referenced standards can be supported in an I/O bank using any number of single-ended or differential standards as long as they use the same V_{REF} and a compatible V_{CCIO} value.

MultiVolt I/O Interface

The Cyclone II architecture supports the MultiVolt I/O interface feature, which allows Cyclone II devices in all packages to interface with systems of different supply voltages. Cyclone II devices have one set of V_{CC} pins (VCCINT) that power the internal device logic array and input buffers that use the LVPECL, LVDS, HSTL, or SSTL I/O standards. Cyclone II devices also have four or eight sets of VCC pins (VCCIO) that power the I/O output drivers and input buffers that use the LVTTL, LVCMOS, or PCI I/O standards.

The Cyclone II VCCINT pins must always be connected to a 1.2-V power supply. If the V_{CCINT} level is 1.2 V, then input pins are 1.5-V, 1.8-V, 2.5-V, and 3.3-V tolerant. The VCCIO pins can be connected to either a 1.5-V, 1.8-V, 2.5-V, or 3.3-V power supply, depending on the output requirements. The output levels are compatible with systems of the same voltage as the power supply (i.e., when VCCIO pins are connected to a 1.5-V power supply, the output levels are compatible with 1.5-V systems). When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3-V and is compatible with 3.3-V systems. Table 2–21 summarizes Cyclone II MultiVolt I/O support.

Table 2–21. Cyclone II MultiVolt I/O Support (Part 1 of 2) *Note (1)*

V_{CCIO} (V)	Input Signal				Output Signal			
	1.5 V	1.8 V	2.5 V	3.3 V	1.5 V	1.8 V	2.5 V	3.3 V
1.5	✓	✓	✓ *(2)*	✓ *(2)*	✓			
1.8	✓ *(4)*	✓	✓ *(2)*	✓ *(2)*	✓ *(3)*	✓		
2.5			✓	✓	✓ *(5)*	✓ *(5)*	✓	

Table 2–21. Cyclone II MultiVolt I/O Support (Part 2 of 2) *Note (1)*

V_{CCIO} (V)	Input Signal				Output Signal			
	1.5 V	1.8 V	2.5 V	3.3 V	1.5 V	1.8 V	2.5 V	3.3 V
3.3			✓ *(4)*	✓	✓ *(6)*	✓ *(6)*	✓ *(6)*	✓

Notes to Table 2–21:

(1) The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}.

(2) When V_{CCIO} = 1.5-V or 1.8-V and a 2.5-V or 3.3-V input signal feeds an input pin, higher pin leakage current is expected.

(3) When V_{CCIO} = 1.8-V, a Cyclone II device can drive a 1.5-V device with 1.8-V tolerant inputs.

(4) When V_{CCIO} = 3.3-V and a 2.5-V input signal feeds an input pin or when VCCIO = 1.8-V and a 1.5-V input signal feeds an input pin, the V_{CCIO} supply current will be slightly larger than expected. The reason for this increase is that the input signal level does not drive to the V_{CCIO} rail, which causes the input buffer to not completely shut off.

(5) When V_{CCIO} = 2.5-V, a Cyclone II device can drive a 1.5-V or 1.8-V device with 2.5-V tolerant inputs.

(6) When V_{CCIO} = 3.3-V, a Cyclone II device can drive a 1.5-V, 1.8-V, or 2.5-V device with 3.3-V tolerant inputs.

Chapter 3. Configuration & Testing

CII51003-1.1

IEEE Std. 1149.1 (JTAG) Boundary Scan Support

All Cyclone™ II devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1. JTAG boundary-scan testing can be performed either before or after, but not during configuration. Cyclone II devices can also use the JTAG port for configuration with the Quartus® II software or hardware using either Jam Files (**.jam**) or Jam Byte-Code Files (**.jbc**).

Cyclone II devices support IOE I/O standard reconfiguration through the JTAG BST chain. The JTAG chain can update the I/O standard for all input and output pins any time before or during user mode through the `CONFIG_IO` instruction. Designers can use this capability for JTAG testing before configuration when some of the Cyclone II pins drive or receive from other devices on the board using voltage-referenced standards. Since the Cyclone II device might not be configured before JTAG testing, the I/O pins may not be configured for appropriate electrical standards for chip-to-chip communication. Programming the I/O standards via JTAG allows designers to fully test I/O connections to other devices.

For information on I/O reconfiguration, see *MorphIO: An I/O Reconfiguration Solution for Altera Devices White Paper*.

A device operating in JTAG mode uses four required pins: `TDI`, `TDO`, `TMS`, and `TCK`. The `TCK` pin has an internal weak pull-down resister, while the `TDI` and `TMS` pins have weak internal pull-up resistors. The `TDO` output pin and all JTAG input pin voltage is determined by the V_{CCIO} of the bank where it resides. The bank V_{CCIO} selects whether the JTAG inputs are 1.5-, 1.8-, 2.5-, or 3.3-V compatible.

Cyclone II devices also use the JTAG port to monitor the logic operation of the device with the SignalTap® II embedded logic analyzer. Cyclone II devices support the JTAG instructions shown in Table 3–1.

Table 3–1. Cyclone II JTAG Instructions (Part 1 of 2)

JTAG Instruction	Instruction Code	Description
SAMPLE/PRELOAD	00 0000 0101	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern to be output at the device pins. Also used by the SignalTap II embedded logic analyzer.
EXTEST *(1)*	00 0000 1111	Allows the external circuitry and board-level interconnects to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	11 1111 1111	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation.
USERCODE	00 0000 0111	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE to be serially shifted out of TDO.
IDCODE	00 0000 0110	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
HIGHZ *(1)*	00 0000 1011	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation, while tri-stating all of the I/O pins.
CLAMP *(1)*	00 0000 1010	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation while holding I/O pins to a state defined by the data in the boundary-scan register.
ICR instructions		Used when configuring a Cyclone II device via the JTAG port with a USB Blaster™, ByteBlaster™ II, MasterBlaster™ or ByteBlasterMV™ download cable, or when using a Jam File or JBC File via an embedded processor.
PULSE_NCONFIG	00 0000 0001	Emulates pulsing the nCONFIG pin low to trigger reconfiguration even though the physical pin is unaffected.

Table 3–1. Cyclone II JTAG Instructions (Part 2 of 2)		
JTAG Instruction	**Instruction Code**	**Description**
CONFIG_IO	00 0000 1101	Allows configuration of I/O standards through the JTAG chain for JTAG testing. Can be executed before, after, or during configuration. Stops configuration if executed during configuration. Once issued, the CONFIG_IO instruction will hold nSTATUS low to reset the configuration device. nSTATUS is held low until the device is reconfigured.
SignalTap II instructions		Monitors internal device operation with the SignalTap II embedded logic analyzer.

Note to Table 3–1:
(1) Bus hold and weak pull-up resistor features override the high-impedance state of HIGHZ, CLAMP, and EXTEST.

The Cyclone II device instruction register length is 10 bits and the USERCODE register length is 32 bits. Tables 3–2 and 3–3 show the boundary-scan register length and device IDCODE information for Cyclone II devices.

Table 3–2. Cyclone II Boundary-Scan Register Length	
Device	**Boundary-Scan Register Length**
EP2C5	450
EP2C8	597
EP2C20	969
EP2C35	1,449
EP2C50	1,374
EP2C70	1,890

Table 3–3. 32-Bit Cyclone II Device IDCODE (Part 1 of 2)				
Device	**IDCODE (32 Bits)** *(1)*			
	Version (4 Bits)	**Part Number (16 Bits)**	**Manufacturer Identity (11 Bits)**	**LSB (1 Bit)** *(2)*
EP2C5	0000	0010 0000 1011 0001	000 0110 1110	1
EP2C8	0000	0010 0000 1011 0010	000 0110 1110	1
EP2C20	0000	0010 0000 1011 0011	000 0110 1110	1
EP2C35	0000	0010 0000 1011 0100	000 0110 1110	1

Table 3–3. 32-Bit Cyclone II Device IDCODE (Part 2 of 2)

Device	IDCODE (32 Bits) *(1)*			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	LSB (1 Bit) *(2)*
EP2C50	0000	0010 0000 1011 0101	000 0110 1110	1
EP2C70	0000	0010 0000 1011 0110	000 0110 1110	1

Notes to Table 3–3:
(1) The most significant bit (MSB) is on the left.
(2) The IDCODE's least significant bit (LSB) is always 1.

Figure 3–1 shows the timing requirements for the JTAG signals.

Figure 3–1. Cyclone II JTAG Waveform

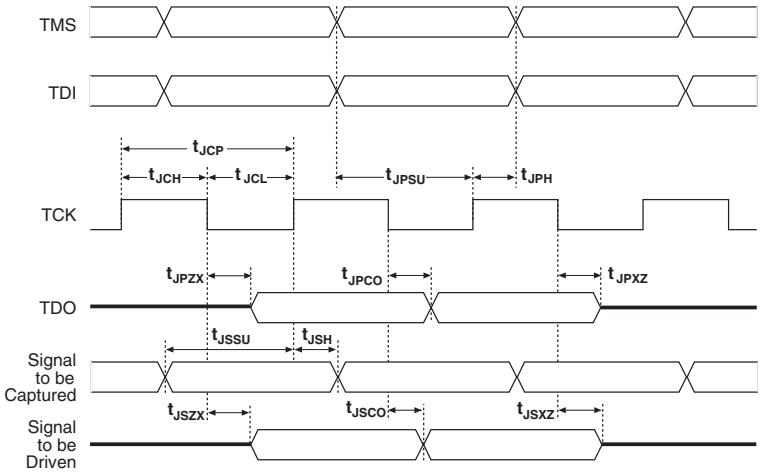


Table 3–4 shows the JTAG timing parameters and values for Cyclone II devices.

Table 3–4. Cyclone II JTAG Timing Parameters & Values

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	40		ns
t_{JCH}	TCK clock high time	20		ns
t_{JCL}	TCK clock low time	20		ns
t_{JPSU}	JTAG port setup time *(2)*	5		ns
t_{JPH}	JTAG port hold time	10		ns
t_{JPCO}	JTAG port clock to output *(2)*		13	ns
t_{JPZX}	JTAG port high impedance to valid output *(2)*		13	ns
t_{JPXZ}	JTAG port valid output to high impedance *(2)*		13	ns
t_{JSSU}	Capture register setup time *(2)*	5		ns
t_{JSH}	Capture register hold time	10		ns
t_{JSCO}	Update register clock to output		25	ns
t_{JSZX}	Update register high impedance to valid output		25	ns
t_{JSXZ}	Update register valid output to high impedance		25	ns

Notes to Table 3–4:

(1) This information is preliminary.

(2) This specification is shown for 3.3-V LVTTL/LVCMOS and 2.5-V LVTTL/LVCMOS operation of the JTAG pins. For 1.8-V LVTTL/LVCMOS and 1.5-V LVCMOS, the JTAG port and capture register clock setup time is 3 ns and port clock to output time is 15 ns.

For more information on JTAG, see the *IEEE 1149.1 (JTAG) Boundary-Scan Testing for Cyclone II Devices* chapter in the *Cyclone II Handbook* and *Jam Programming & Test Language Specification*.

SignalTap II Embedded Logic Analyzer

Cyclone II devices support the SignalTap II embedded logic analyzer, which monitors design operation over a period of time through the IEEE Std. 1149.1 (JTAG) circuitry. A designer can analyze internal logic at speed without bringing internal signals to the I/O pins. This feature is particularly important for advanced packages, such as FineLine BGA® packages, because it can be difficult to add a connection to a pin during the debugging process after a board is designed and manufactured.

For more information on the SignalTap II, see the *Signal Tap* chapter of the *Quartus II Handbook, Volume 3*.

Configuration

The logic, circuitry, and interconnects in the Cyclone II architecture are configured with CMOS SRAM elements. Cyclone II devices are reconfigurable and are 100% tested prior to shipment. As a result, the designer does not have to generate test vectors for fault coverage purposes, and can instead focus on simulation and design verification. In addition, the designer does not need to manage inventories of different ASIC designs. Cyclone II devices can be configured on the board for the specific functionality required.

Cyclone II devices are configured at system power-up with data stored in an Altera configuration device or provided by a system controller. The Cyclone II device's optimized interface allows the device to act as controller in an active serial configuration scheme with EPCS serial configuration devices. The serial configuration device can be programmed via SRunner, the ByteBlaster II or USB Blaster download cable, the Altera Programming Unit (APU), or third-party programmers.

In addition to EPCS serial configuration devices, Altera offers in-system programmability (ISP)-capable configuration devices that can configure Cyclone II devices via a serial data stream using the Passive serial (PS) configuration mode. The PS interface also enables microprocessors to treat Cyclone II devices as memory and configure them by writing to a virtual memory location, simplifying reconfiguration. After a Cyclone II device has been configured, it can be reconfigured in-circuit by resetting the device and loading new configuration data. Real-time changes can be made during system operation, enabling innovative reconfigurable applications.

Operating Modes

The Cyclone II architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. Together, the configuration and initialization processes are called command mode. Normal device operation is called user mode.

SRAM configuration elements allow Cyclone II devices to be reconfigured in-circuit by loading new configuration data into the device. With real-time reconfiguration, the device is forced into command mode with the `nCONFIG` pin. The configuration process loads different configuration data, reinitializes the device, and resumes user-mode operation. Designers can perform in-field upgrades by distributing new configuration files within the system or remotely.

A built-in weak pull-up resistor pulls all user I/O pins to V_{CCIO} before and during device configuration.

The configuration pins support 1.5-V/1.8-V or 2.5-V/3.3-V I/O standards. The voltage level of the configuration output pins is determined by the V_{CCIO} of the bank where the pins reside. The bank V_{CCIO} selects whether the configuration inputs are 1.5-V, 1.8-V, 2.5-V, or 3.3-V compatible.

Configuration Schemes

Designers can load the configuration data for a Cyclone II device with one of three configuration schemes (see Table 3–5), chosen on the basis of the target application. Designers can use a configuration device, intelligent controller, or the JTAG port to configure a Cyclone II device. A low-cost configuration device can automatically configure a Cyclone II device at system power-up.

Multiple Cyclone II devices can be configured in any of the three configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

Table 3–5. Data Sources for Configuration

Configuration Scheme	Data Source
Active serial (AS)	Low-cost serial configuration device
Passive serial (PS)	Enhanced or EPC2 configuration device, MasterBlaster, ByteBlasterMV, ByteBlaster II or USB Blaster download cable, or serial data source
JTAG	MasterBlaster, ByteBlasterMV, ByteBlaster II or USB Blaster download cable or a microprocessor with a Jam or JBC file

For more information on configuration, see the *Configuring Cyclone II Devices* chapter of the *Cyclone II Handbook, Volume 2*.

Cyclone II Automated Single Event Upset Detection

Cyclone II devices offer on-chip circuitry for automated checking of single event upset (SEU) detection. Some applications that require the device to operate error free at high elevations or in close proximity to earth's North or South Pole will require periodic checks to ensure continued data integrity. The error detection cyclic redundancy check (CRC) feature controlled by the **Device & Pin Options** dialog box in the Quartus II software uses a 32-bit CRC circuit to ensure data reliability and is one of the best options for mitigating SEU.

Designers can implement the error detection CRC feature with existing circuitry in Cyclone II devices, eliminating the need for external logic. For Cyclone II devices, the CRC is computed by the device during configuration and checked against an automatically computed CRC during normal operation. The CRC_ERROR pin reports a soft error when configuration SRAM data is corrupted, triggering device reconfiguration.

Custom-Built Circuitry

Dedicated circuitry in the Cyclone II devices performs error detection automatically. This error detection circuitry in Cyclone II devices constantly checks for errors in the configuration SRAM cells while the device is in user mode. Designers can monitor one external pin for the error and use it to trigger a re-configuration cycle. The designer can select the desired time between checks by adjusting a built-in clock divider.

Software Interface

In the Quartus II software version 4.1 and later, designers can turn on the automated error detection CRC feature in the Device & Pin Options dialog box. This dialog box allows you to enable the feature and set the internal frequency of the CRC checker between 400 kHz to 100 MHz. This controls the rate that the CRC circuitry verifies the internal configuration SRAM bits in the FPGA device.

For more information on CRC, refer to the *Error Detection Using CRC in Altera FPGAs* Application Note.

Chapter 4. Hot Socketing, ESD & Power-On Reset

CII51004-1.0

Introduction

Cyclone™ II devices offer hot socketing (also known as hot plug-in, hot insertion, or hot swap) and power sequencing support without the use of any external devices. Designers can insert or remove a Cyclone II board in a system during system operation without causing undesirable effects to the board or to the running system bus.

The hot-socketing feature lessens the board design difficulty when using Cyclone II devices on printed circuit boards (PCBs) that also contain a mixture of 3.3-, 2.5-, 1.8-, and 1.5-V devices. With the Cyclone II hot-socketing feature, designers no longer need to ensure a proper power-up sequence for each device on the board.

The Cyclone II hot-socketing feature provides:

- Board or device insertion and removal without external components or board manipulation
- Support for any power-up sequence
- Non-intrusive I/O buffers to system buses during hot insertion

This chapter also discusses the electro-static discharge (ESD) protection and the power-on reset (POR) circuitry in Cyclone II devices. The POR circuitry keeps the devices in the reset state until the V_{CC} is within operating range.

Cyclone II Hot-Socketing Specifications

Cyclone II devices offer hot-socketing capability with all three features listed above without any external components or special design requirements. The hot-socketing feature in Cyclone II devices offers the following:

- Designers can device before power-up without any damage to the device itself.
- I/O pins remain tri-stated during power-up. The device does not drive out before or during power-up, thereby affecting other buses in operation.
- There are no internal current paths from I/O pins to V_{CCIO} or V_{CCINT} power supplies. Signals driven in on I/O pins will not power the V_{CCIO} or V_{CCINT} power buses.

Devices Can Be Driven before Power-Up

You can drive signals into the I/O pins, dedicated input pins, and dedicated clock pins of Cyclone II devices before or during power-up or power-down without damaging the device. Cyclone II devices support any power-up or power-down sequence (V_{CCIO} and V_{CCINT}) to simplify system level design.

I/O Pins Remain Tri-Stated during Power-Up

A device that does not support hot socketing may interrupt system operation or cause contention by driving out before or during power-up. In a hot-socketing situation, the Cyclone II device's output buffers are turned off during system power-up or power-down. The Cyclone II device also does not drive out until the device is configured and has attained proper operating conditions.

Signal Pins Do Not Have Internal Current Paths to V_{CCIO} or V_{CCINT} Power Supplies

Devices that do not support hot socketing can short power supplies together when powered-up through the device signal pins. This irregular power-up can damage both the driving and driven devices and can disrupt card power-up.

Cyclone II devices do not have a current path from I/O pins, dedicated input pins, or dedicated clock pins to the V_{CCIO} or V_{CCINT} pins before or during power-up. A Cyclone II device may be inserted into (or removed from) a powered-up system board without damaging or interfering with system-board operation. When hot socketing, Cyclone II devices may have a minimal effect on the signal integrity of the backplane.

You can power up or power down the V_{CCIO} and V_{CCINT} pins in any sequence. The power supply ramp rates can range from 100 ns to 100 ms. Both V_{CC} supplies must power down within 100 ms of each other to prevent I/O pins from driving out. During hot socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF. I/O pins can be driven by active signals with a rise and fall time of 2 to 40 ns. Cyclone II devices meet the following hot-socketing specification.

The hot-socketing DC specification is: $| I_{IOPIN} | < 300$ µA

The hot-socketing AC specification is: $| I_{IOPIN} | < 8$ mA or $| I_{IOPIN} | > 8$ mA for 10 ns or less

I_{IOPIN} is the current at any user I/O pin on the device. The AC specification has two requirements. The peak current during power-up or power-down is < 8 mA. The peak current can exceed 8 mA for 10 ns or less.

A possible concern for semiconductor devices in general regarding hot socketing is the potential for latch-up. Latch-up can occur when electrical subsystems are hot socketed into an active system. During hot socketing, the signal pins may be connected and driven by the active system before the power supply can provide current to the device's V_{CC} and ground planes. This condition can lead to latch-up and cause a low-impedance path from V_{CC} to ground within the device. As a result, the device extends a large amount of current, possibly causing electrical damage.

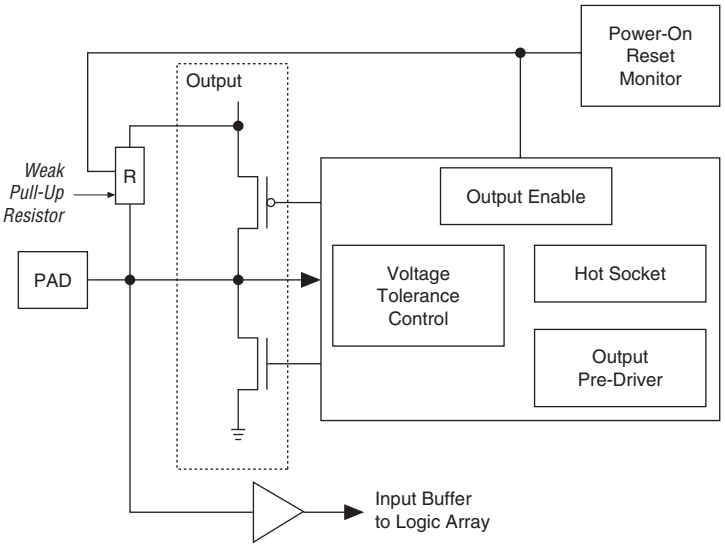
Altera has ensured by design of the I/O buffers and hot-socketing circuitry, that Cyclone II devices are immune to latch-up during hot socketing.

Hot-Socketing Feature Implementation in Cyclone II Devices

The hot-socketing feature turns off the output buffer during power up (either V_{CCINT} or V_{CCIO} supplies) or power down. The hot-socket circuit will generate an internal HOTSCKT signal when either V_{CCINT} or V_{CCIO} is below the threshold voltage. Designs cannot use the HOTSCKT signal for other purposes. The HOTSCKT signal will cut off the output buffer to ensure that no DC current (except for weak pull-up leakage current) leaks through the pin. When V_{CC} ramps up slowly, V_{CC} is still relatively low even after the internal POR signal (not available to the FPGA fabric used by customer designs) is released and the configuration is finished. The CONF_DONE, nCEO, and nSTATUS pins fail to respond, as the output buffer cannot drive out because the hot-socketing circuitry will keep the I/O pins tristated at this low V_{CC} voltage. Therefore, the hot-socketing circuit has been removed on these configuration output or bidirectional pins to ensure that they are able to operate during configuration. These pins are expected to drive out during power-up and power-down sequences.

Each I/O pin has the circuitry shown in Figure 4–1.

Figure 4–1. Hot-Socketing Circuit Block Diagram for Cyclone II Devices

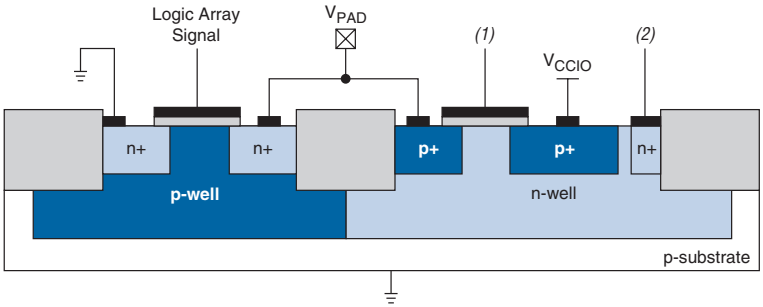


The POR circuit monitors V_{CCINT} voltage level and keeps I/O pins tri-stated until the device is in user mode. The weak pull-up resistor (R) from the I/O pin to V_{CCIO} keeps the I/O pins from floating. The voltage tolerance control circuit permits the I/O pins to be driven by 3.3 V before V_{CCIO} and/or V_{CCINT} are powered, and it prevents the I/O pins from driving out when the device is not in user mode. The hot socket circuit prevents I/O pins from internally powering V_{CCIO} and V_{CCINT} when driven by external signals before the device is powered.

For more information, see the *DC Characteristics & Timing Specifications* chapter in Volume 1 of the *Cyclone II Device Handbook* for the value of the internal weak pull-up resistors.

Figure 4–2 shows a transistor level cross section of the Cyclone II device I/O buffers. This design ensures that the output buffers do not drive when V_{CCIO} is powered before V_{CCINT} or if the I/O pad voltage is higher than V_{CCIO}. This also applies for sudden voltage spikes during hot socketing. There is no current path from signal I/O pins to V_{CCINT} or V_{CCIO} during hot socketing. The V_{PAD} leakage current charges the voltage tolerance control circuit capacitance.

Figure 4–2. Transistor Level Diagram of FPGA Device I/O Buffers



Note to Figure 4–2:
(1) This is the logic array signal or the larger of either the V_{CCIO} or V_{PAD} signal.
(2) This is the larger of either the V_{CCIO} or V_{PAD} signal.

ESD Protection

Electro-static discharge (ESD) occurs when a charge moves from one surface to another. ESD is a charge that moves between two surfaces with different potentials. Destructive ESD can occur when the voltage differential between the two surfaces is sufficiently high to break down the dielectric strength of the medium separating the two surfaces. When a static charge moves, it becomes a current that damages or destroys gate oxide, metallization, and junctions.

ESD can occur in one of four ways: a charged body can touch an integrated circuit (IC), a charged IC can touch a grounded surface, a charged machine can touch an IC, or an electrostatic field can induce a voltage across a dielectric sufficient to break it down.

ESD Testing

ESD can cause destructive damage to semiconductor IC devices like FPGAs. The industry has introduced testing standards to minimize the detrimental effects of ESD by ensuring all devices have undergone proper standardized testing for quality and reliability. Three major ESD testing methods exist for defining a passing level. Altera tests to human-body model (HBM) and charged-device model (CDM). Machine model (MM) testing is not typically performed because the results are similar to HBM testing.

Human-Body Model

The HBM simulates the action of a human body discharging accumulated static charge through a device to ground. This model uses a series RC network consisting of a 100-pF capacitor and a 1,500-Ω resistor. Altera production devices meet the HBM ESD specifications of 1,000 V.

Machine Model

The MM simulates a machine discharging accumulated static charge through a device to ground. This model uses a series RC network of a 200-pF capacitor, and nominal series resistance of less than 1 Ω. The output waveform usually is described in terms of peak current and oscillating frequency for a given discharge voltage.

Charged-Device Model

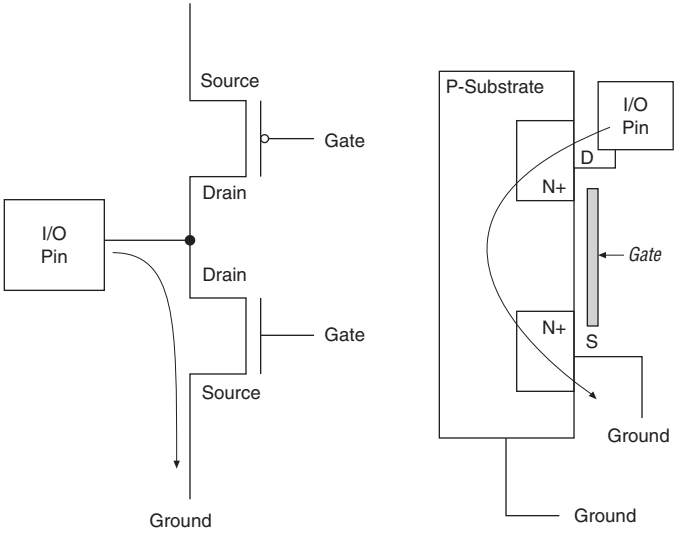
The CDM simulates charging and discharging events that occur during the manufacturing and testing processes. Potential for CDM events occur when there is metal-to-metal contact in manufacturing. One example is a device sliding down a shipping tube and hitting a metal surface. The CDM addresses the possibility that a charge may reside on a lead frame or package (e.g., from shipping) and discharge through a pin that subsequently is grounded, causing damage to sensitive circuitry in the path. The discharge current is limited only by the parasitic impedance and capacitance of the device. CDM testing consists of charging a package to a specified voltage, then discharging this voltage through the relevant package leads. Altera production devices meet the CDM ESD specification of 500 V.

ESD Circuitry

The CMOS output drivers in the I/O pins intrinsically provide ESD protection. ESD voltage strikes can cause a positive voltage zap or a negative voltage zap.

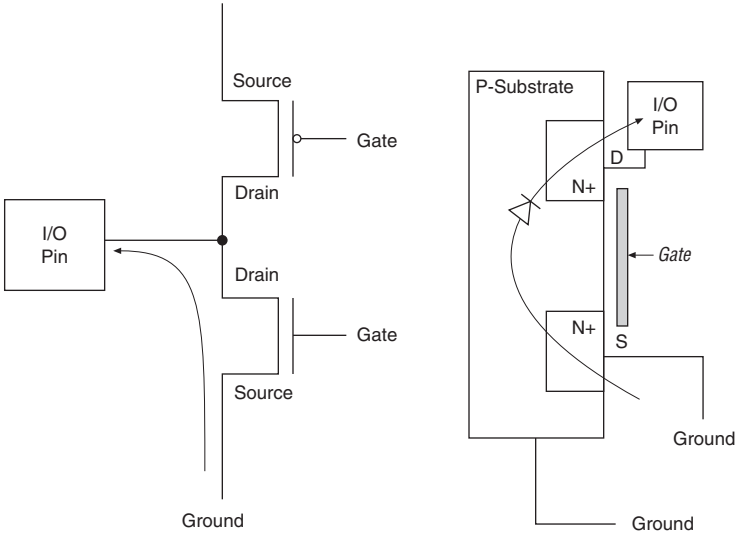
A positive ESD voltage zap occurs when a positive voltage is present on an I/O pin because of an ESD charge event. This can cause the N+ (drain)/P-substrate junction of the N-channel drain to break down and the N+ (drain)/P-substrate/N+ (source) intrinsic bipolar transistor to turn on to discharge ESD current from I/O pin to ground. The arrows in Figure 4–3 show the ESD current discharge path during a positive ESD zap.

Figure 4–3. ESD Protection During Positive Voltage Zap



When the I/O pin receives a negative ESD zap at the pin that is less than –0.7 V (0.7 V is the voltage drop across a diode), the intrinsic P- substrate/N+ drain diode is forward biased. Hence, the discharge ESD current path is from ground to the I/O pin, as shown in Figure 4–4.

Figure 4–4. ESD Protection During Negative Voltage Zap



For the maximum specification of ESD protection, see the *DC Characteristics & Timing Specifications* chapter in Volume 1 of the *Cyclone II Device Handbook*. For more information on quality and reliability, see the *Reliability Report* for Altera devices.

Power-On Reset Circuitry

Cyclone II devices have a POR circuit to keep the whole device system in reset state until the power supply voltage levels have stabilized during power-up. The POR circuit monitors the V_{CCINT} and V_{CCIO} voltage levels and tri-states all the user I/O pins while V_{CC} is ramping up until normal user levels are reached. The POR circuitry also ensures that the V_{CCIO} level of the two I/O banks that contains configuration pins (I/O banks 1 and 3 for EP2C5 and EP2C8, I/O banks 1 and 6 for EP2C20, EP2C35, EP2C50, and EP2C70) as well as the logic array V_{CCINT} voltage reach an acceptable level before configuration is triggered. After the Cyclone II device enters user mode, the POR circuit continues to monitor the V_{CCINT} voltage level so that a brown-out condition during user mode can be detected. If there is a V_{CCINT} voltage sag below the POR trip point at ~600 to 700 mV during user mode, the POR circuit resets the device. If there is a V_{CCIO} voltage sag during user mode, the POR circuit will not reset the device.

When power is applied to a Cyclone II device, a POR event occurs if V_{CC} reaches the recommended operating range within a certain period of time (specified as a maximum V_{CC} rise time). The maximum V_{CC} rise time for Cyclone II devices is 100 ms. The minimum POR time is 100 ms for Cyclone II devices. However, the designer can extend initialization time by asserting the nSTATUS pin using an external component.

Conclusion

Cyclone II devices are hot socketable and support all power-up and power-down sequences with the one requirement that V_{CCIO} and V_{CCINT} be powered up and down within 100 ms of each other to keep the I/O pins from driving out. Cyclone II devices do not require any external devices for hot socketing and power sequencing and have robust ESD protection.

Chapter 5. DC Characteristics & Timing Specifications

CII51005-1.1

Operating Conditions

Cyclone™ II devices are offered in both commercial and industrial grades. Commercial devices are offered in -6 (fastest), -7, -8 speed grades.

All parameter limits are representative of worst-case supply voltage and junction temperature conditions. Unless otherwise noted, the parameter values in this chapter apply to all Cyclone II devices. AC and DC characteristics are specified using the same numbers for both commercial and industrial grades. All parameters representing voltages are measured with respect to ground.

Tables 5–1 through 5–4 provide information on absolute maximum ratings.

Table 5–1. Cyclone II Device Absolute Maximum Ratings *Notes (1), (2)*

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCINT}	Supply voltage	With respect to ground	–0.5	1.8	V
V_{CCIO}	Output supply voltage		–0.5	4.6	V
V_{IN}	DC input voltage		–0.5	4.6	V
I_{OUT}	DC output current, per pin		–25	40	mA
T_{STG}	Storage temperature	No bias	–65	150	°C
T_J	Junction temperature	BGA packages under bias		125	°C

Notes to Table 5–1:

(1) Conditions beyond those listed in this table will cause permanent damage to a device. These are stress ratings only. Functional operation at these levels or any other conditions beyond those specified in this chapter is not implied. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse affects on the device reliability.

(2) See the *Operating Requirements for Altera Devices Data Sheet* for more information.

Table 5–2 specifies the recommended operating conditions for Cyclone II devices. It shows the allowed voltage ranges for V_{CCINT}, V_{CCIO}, and the operating junction temperature (T_J). The LVTTL and LVCMOS inputs are powered by V_{CCIO} only. The LVPECL input buffers on dedicated clock pins are powered by V_{CCINT}. The SSTL, HSTL, LVDS input buffers are powered by both V_{CCINT} and V_{CCIO}.

Table 5–2. Recommended Operating Conditions

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	*(1)*	1.15	1.25	V
V_{CCIO} *(2)*	Supply voltage for output buffers, 3.3-V operation	*(1)*	3.00 *(3)*	3.60 *(3)*	V
	Supply voltage for output buffers, 2.5-V operation	*(1)*	2.375	2.625	V
	Supply voltage for output buffers, 1.8-V operation	*(1)*	1.71 *(2)*	1.89	V
	Supply voltage for output buffers, 1.5-V operation	*(1)*	1.4	1.6	V
T_J *(4)*	Operating junction temperature	For commercial use	0	85	°C
		For industrial use	–40	100	°C

Notes to Table 5–2:

(1) The maximum V_{CC} (both V_{CCIO} and V_{CCINT}) rise time is 100 ms, and V_{CC} must rise monotonically.

(2) The V_{CCIO} range given here spans the lowest and highest operating voltages of all supported I/O standards. The recommended V_{CCIO} range specific to each of the single-ended I/O standards is given in Table 5–6, and those specific to the differential standards is given in Table 5–8.

(3) The minimum and maximum values of 3.0 V and 3.6 V, respectively, for V_{CCIO} only applies to the PCI and PCI-X I/O standards. See Table 5–6 for the voltage range of other I/O standards.

(4) Contact Altera Applications for θ_{JA} and θ_{JC} values.

Table 5–3. DC Characteristics for User I/O, Dual-Purpose & Dedicated Pins (Part 1 of 2)

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{IN}	Input voltage	*(1)*, *(2)*	–0.5		4.0	V
I_I	Input pin leakage current	$V_I = V_{CCIOmax}$ to 0 V *(3)*	–10		10	µA
V_{OUT}	Output voltage		0		V_{CCIO}	V
I_{OZ}	Tri-stated I/O pin leakage current	$V_O = V_{CCIOmax}$ to 0 V *(3)*	–10		10	µA

Table 5–3. DC Characteristics for User I/O, Dual-Purpose & Dedicated Pins (Part 2 of 2)

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
I_{CC0}	V_{CC} supply current (standby) (all memory blocks in power-down mode)	V_I = ground, no load, no toggling inputs				mA
R_{CONF}	Value of I/O pin pull-up resistor before and during configuration	V_{CCIO} = 3.0 V *(4)*	20		50	kΩ
		V_{CCIO} = 2.375 V *(4)*	30		80	kΩ
		V_{CCIO} = 1.71 V *(4)*	60		150	kΩ

Notes to Table 5–3:

(1) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.

(2) The minimum DC input is –0.5 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to the voltages shown in Table 5–4, based on input duty cycle for input currents less than 100 mA. The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to 100% duty cycle.

(3) This value is specified for normal device operation. The value may vary during power-up. This applies for all V_{CCIO} settings (3.3, 2.5, 1.8, and 1.5 V).

(4) Pin pull-up resistance values will lower if an external source drives the pin higher than V_{CCIO}.

Table 5–4 shows the maximum V_{IN} overshoot voltage and the dependency on the duty cycle of the input signal. See Table 5–3 for more information.

Table 5–4. V_{IN} Overshoot Voltage for All Input Buffers

Maximum V_{IN} (V)	Input Signal Duty Cycle
4.0	100% (DC)
4.1	90%
4.2	50%
4.3	30%
4.4	17%
4.5	10%

Single-Ended I/O Standards

Tables 5–6 and 5–7 provide operating condition information when using single-ended I/O standards with Cyclone II devices. Table 5–5 provides descriptions for the voltage and current symbols used in Tables 5–6 and 5–7.

Table 5–5. Voltage & Current Symbol Definitions

Symbol	Definition
V_{CCIO}	Supply voltage for single-ended inputs and for output drivers
V_{REF}	Reference voltage for setting the input switching threshold
V_{IL}	Input voltage that indicates a low logic level
V_{IH}	input voltage that indicates a high logic level
V_{OL}	Output voltage that indicates a low logic level
V_{OH}	Output voltage that indicates a high logic level
I_{OL}	Output current condition under which V_{OL} is tested
I_{OH}	Output current condition under which V_{OH} is tested
V_{TT}	Voltage applied to a resistor termination as specified by HSTL and SSTL standards

Table 5–6. Recommended Operating Conditions for User I/O Pins Using Single-Ended I/O Standards (Part 1 of 2) *Note (1)*

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{IL} (V)	V_{IH} (V)
	Min	Nom	Max	Min	Nom	Max	Max	Min
3.3-V LVTTL and LVCMOS	3.135	3.3	3.465				0.8	1.7
2.5-V LVTTL and LVCMOS	2.375	2.5	2.625				0.7	1.7
1.8-V LVTTL and LVCMOS	1.710	1.8	1.890				$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$
1.5-V LVCMOS	1.425	1.5	1.575				$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$
PCI and PCI-X	3.000	3.3	3.600				$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$
SSTL-2 class I	2.375	2.5	2.625	1.19	1.25	1.31	$V_{REF} - 0.18$	$V_{REF} + 0.18$
SSTL-2 class II	2.375	2.5	2.625	1.19	1.25	1.31	$V_{REF} - 0.18$	$V_{REF} + 0.18$
SSTL-18 class I	1.7	1.8	1.9	0.833	0.9	0.969	$V_{REF} - 0.125$	$V_{REF} + 0.125$
SSTL-18 class II	1.7	1.8	1.9	0.833	0.9	0.969	$V_{REF} - 0.125$	$V_{REF} + 0.125$
1.8-V HSTL class I	1.71	1.8	1.89	0.85	0.9	0.95	$V_{REF} - 0.1$	$V_{REF} + 0.1$

Table 5–6. Recommended Operating Conditions for User I/O Pins Using Single-Ended I/O Standards (Part 2 of 2) *Note (1)*

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{IL} (V)	V_{IH} (V)
	Min	Nom	Max	Min	Nom	Max	Max	Min
1.8-V HSTL class II	1.71	1.8	1.89	0.85	0.9	0.95	V_{REF} – 0.1	V_{REF} + 0.1
1.5-V HSTL class I	1.425	1.5	1.575	0.71	0.75	0.79	V_{REF} – 0.1	V_{REF} + 0.1
1.5-V HSTL class II	1.425	1.5	1.575	0.71	0.75	0.79	V_{REF} – 0.1	V_{REF} + 0.1

Note to Table 5–6:
(1) Nominal values (Nom) are for T_A = 25° C, V_{CCINT} = 1.2 V, and V_{CCIO} = 1.5, 1.8, 2.5, and 3.3 V.

Table 5–7. DC Characteristics of User I/O Pins Using Single-Ended Standards (Part 1 of 2) *Note (1)*

I/O Standard	Current Drive Strength Setting (mA)	Test Conditions		Voltage Thresholds	
		I_{OL} (mA)	I_{OH} (mA)	Maximum V_{OL} (V)	Minimum V_{OH} (V)
3.3-V LVTTL and LVCMOS	4	4	–4	0.4	2.4
	8	8	–8		
	12	12	–12		
	16	16	–16		
	20	20	–20		
	24	24	–24		
2.5-V LVTTL and LVCMOS	4	4	–4	0.4	V_{CCIO} – 0.4
	8	8	–8		
	12	12	–12		
	16	16	–16		
1.8-V LVTTL and LVCMOS	2	2	–2	0.4	V_{CCIO} – 0.4
	4	4	–4		
	6	6	–6		
	8	8	–8		
	10	10	–10		
	12	12	–12		
1.5-V LVCMOS	2	2	–2	0.25 × V_{CCIO}	0.75 × V_{CCIO}
	4	4	–4		
	6	6	–6		
	8	8	–8		
PCI and PCI-X		1.5	–0.5	0.1 × V_{CCIO}	0.9 × V_{CCIO}

Table 5–7. DC Characteristics of User I/O Pins Using Single-Ended Standards (Part 2 of 2) *Note (1)*

I/O Standard	Current Drive Strength Setting (mA)	Test Conditions		Voltage Thresholds	
		I_{OL} (mA)	I_{OH} (mA)	Maximum V_{OL} (V)	Minimum V_{OH} (V)
SSTL-2 class I	8	8	–8	V_{TT} – 0.57	V_{TT} + 0.57
	12	12	–12		
SSTL-2 class II	16	16	–16	V_{TT} – 0.76	V_{TT} + 0.76
	20	20	–20		
	24	24	–24		
SSTL-18 class I	4	4	–4	V_{TT} – 0.475	V_{TT} + 0.475
	6	6	–6		
	8	8	–8		
	10	10	–10		
	12	12	–12		
SSTL-18 class II	8	8	–8	0.28	V_{CCIO} – 0.28
	16	16	–16		
	18	18	–18		
1.8-V HSTL class I	4	4	–4	0.4	V_{CCIO} – 0.4
	6	6	–6		
	8	8	–8		
	10	10	–10		
	12	12	–12		
1.8-V HSTL class II	16	16	–16	0.4	V_{CCIO} – 0.4
	18	18	–18		
	20	20	–20		
1.5-V HSTL class I	4	4	–4	0.4	V_{CCIO} – 0.4
	6	6	–6		
	8	8	–8		
	10	10	–10		
	12	12	–12		
1.5V HSTL class II	16	16	–16	0.4	V_{CCIO} – 0.4

Note to Table 5–7:
(1) The values in this table are based on the conditions listed in Tables 5–2 and 5–6.

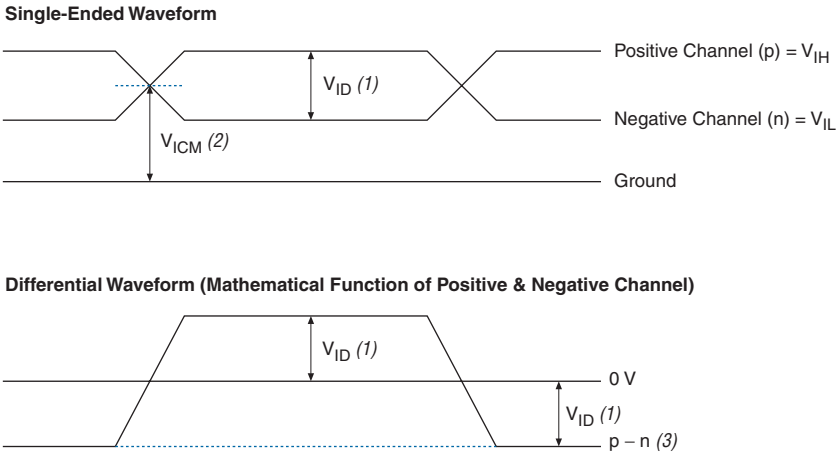
Differential I/O Standards

The RSDS and mini-LVDS I/O standards are only supported on output pins. The LVDS I/O standard is supported on both receiver input pins and transmitter output pins.

For more information on how these differential I/O standards are implemented, see the *High-Speed Differential Interfaces in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Figure 5–1 shows the receiver input waveforms for all differential I/O standards (LVDS, LVPECL, differential 1.5-V HSTL class I and II, differential 1.8-V HSTL class I and II, differential SSTL-2 class I and II, and differential SSTL-18 class I and II).

Figure 5–1. Receiver Input Waveforms for Differential I/O Standards



Notes to Figure 5–1:

(1) V_{ID} is the differential input voltage. $V_{ID} = |p - n|$.

(2) V_{ICM} is the input common mode voltage. $V_{ICM} = (p - n)/2$.

(3) The p – n waveform is a function of the positive channel (p) and the negative channel (n).

Table 5–8 shows the recommended operating conditions for user I/O pins with differential I/O standards.

Table 5–8. Recommended Operating Conditions for User I/O Pins Using Differential Signal I/O Standards

I/O Standard	V_{CCIO} (V)			V_{ID} (V) *(1)*			V_{ICM} (V)			V_{IL} (V)		V_{IH} (V)	
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Max	Min	Max
LVDS	2.375	2.5	2.625	0.1			0.1	1.25	1.8				
mini-LVDS *(2)*	2.375	2.5	2.625										
RSDS *(2)*	2.375	2.5	2.625										
LVPECL *(3)*	3.135	3.3	3.465	0.1	0.6	0.95				0	2.2	2.1	2.88
Differential 1.5-V HSTL class I and II *(4)*	1.425	1.5	1.575	0.2		V_{CCIO} + 0.6	0.68		0.9		V_{REF} – 0.1	V_{REF} + 0.1	
Differential 1.8-V HSTL class I and II *(4)*	1.71	1.8	1.89								V_{REF} – 0.1	V_{REF} + 0.1	
Differential SSTL-2 class I and II *(5)*	2.375	2.5	2.625	0.36		V_{CCIO} + 0.6	0.5 × V_{CCIO} – 0.2	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.2		V_{REF} – 0.1	V_{REF} + 0.1	
Differential SSTL-18 class I and II *(5)*	1.7	1.8	1.9	0.25		V_{CCIO} + 0.6	0.5 × V_{CCIO} – 0.2	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.2		V_{REF} – 0.1	V_{REF} + 0.1	

Notes to Table 5–8:

(1) Refer to the *High-Speed Differential Interfaces in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook* for measurement conditions on V_{ID}.

(2) The RSDS and mini-LVDS I/O standards are only supported on output pins.

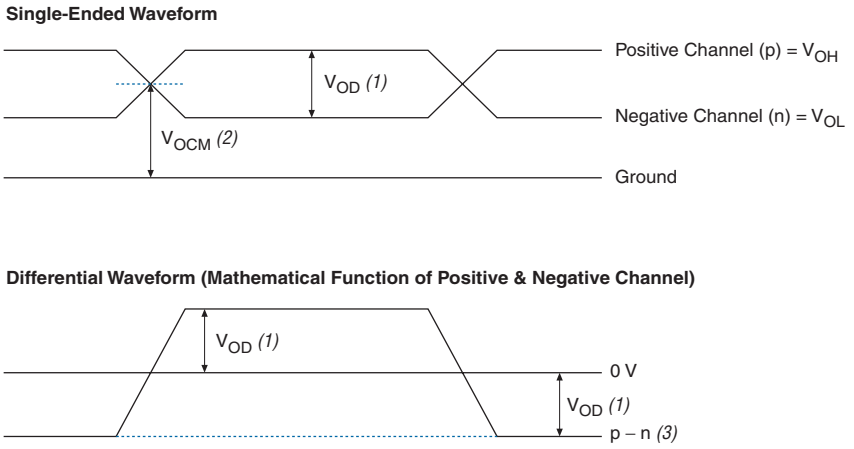
(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

(5) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.

Figure 5–2 shows the transmitter output waveforms for all supported differential output standards (LVDS, mini-LVDS, RSDS, differential 1.5-V HSTL class I and II, differential 1.8-V HSTL class I and II, differential SSTL-2 class I and II, and differential SSTL-18 class I and II).

Figure 5–2. Transmitter Output Waveforms for Differential I/O Standards



Notes to Figures 5–1 & 5–2:
(1) V_{OD} is the output differential voltage. $V_{OD} = |p - n|$.
(2) V_{OCM} is the output common mode voltage. $V_{OCM} = (p - n)/2$.
(3) The p – n waveform is a function of the positive channel (p) and the negative channel (n).

Table 5–9 shows the DC characteristics for user I/O pins with differential I/O standards.

Table 5–9. DC Characteristics for User I/O Pins Using Differential I/O Standards (Part 1 of 2) *Note (1)*

I/O Standard	V_{OD} (mV)			ΔV_{OD} (mV)		V_{OCM} (V)			V_{OH} (V)		V_{OL} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Max
LVDS	247		600		50	1.125	1.25	1.375				
mini-LVDS *(2)*	300		600		50	1	1.2	1.4				
RSDS *(2)*	100	200	600			0.5	1.2	1.5				
Differential 1.5-V HSTL class I and II *(3)*									V_{CCIO} – 0.4			0.4
Differential 1.8-V HSTL class I and II *(3)*									V_{CCIO} – 0.4			0.4
Differential SSTL-2 class I *(4)*									V_{TT} + 0.57			V_{TT} – 0.57

Table 5–9. DC Characteristics for User I/O Pins Using Differential I/O Standards (Part 2 of 2) *Note (1)*

I/O Standard	V_{OD} (mV)			ΔV_{OD} (mV)		V_{OCM} (V)			V_{OH} (V)		V_{OL} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Max
Differential SSTL-2 class II *(4)*									V_{TT} + 0.76			V_{TT} – 0.76
Differential SSTL-18 class I *(4)*						0.5 × V_{CCIO} – 0.125	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.125	V_{TT} + 0.475			V_{TT} – 0.475
Differential SSTL-18 class II *(4)*						0.5 × V_{CCIO} – 0.125	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.125	V_{CCIO} – 0.28			0.28

Notes to Table 5–9:

(1) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(2) The RSDS and mini-LVDS I/O standards are only supported on output pins.

(3) The differential 1.8-V HSTL and differential 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

(4) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.

DC Characteristics for Different Pin Types

Table 5–10 shows which types of pins that support bus hold circuitry.

Table 5–10. Bus Hold Support

Pin Type	Bus Hold
I/O pins using single-ended I/O standards	Yes
I/O pins using differential I/O standards	No
Dedicated clock pins	No
JTAG	No
Configuration pins	No

Table 5–11 specifies the bus hold parameters for general I/O pins.

Table 5–11. Bus Hold Parameters *Note (1)*

Parameter	Conditions	V_{CCIO} Level						Unit
		1.8 V		2.5 V		3.3 V		
		Min	Max	Min	Max	Min	Max	
Bus-hold low, sustaining current	$V_{IN} > V_{IL}$(maximum)	30		50		70		µA
Bus-hold high, sustaining current	$V_{IN} < V_{IL}$(minimum)	–30		–50		–70		µA
Bus-hold low, overdrive current	$0 V < V_{IN} < V_{CCIO}$		200		300		500	µA
Bus-hold high, overdrive current	$0 V < V_{IN} < V_{CCIO}$		–200		–300		–500	µA
Bus-hold trip point *(2)*		0.68	1.07	0.7	1.7	0.8	2.0	V

Notes to Table 5–11:
(1) There is no specification for bus-hold at V_{CCIO} = 1.5 V for the HSTL I/O standard.
(2) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Table 5–12 shows the Cyclone II device pin capacitance for different I/O pin types.

Table 5–12. Device Capacitance *Note (1)*

Symbol	Parameter	Typical	Unit
C_{IO}	Input capacitance for user I/O pin	*(2)*	pF
C_{LVDS}	Input capacitance for dual-purpose LVDS/user I/O pin	*(2)*	pF
C_{VREF}	Input capacitance for dual-purpose VREF and user I/O pin.	*(2)*	pF
C_{DPCLK}	Input capacitance for dual-purpose DPCLK and user I/O pin.	*(2)*	pF
C_{CLK}	Input capacitance for clock pin.	*(2)*	pF

Notes to Table 5–12:
(1) Capacitance is sample-tested only. Capacitance is measured using time-domain reflectometry (TDR). Measurement accuracy is within ±0.5 pF.
(2) This specification will be available in a future version of the data sheet.

Table 5–13 shows the specification for ESD for all Cyclone II device pins.

Table 5–13. ESD Protection

Symbol	Parameter	Maximum	Unit
ESD_{HBM}	Human body model	1,000	V
ESD_{CDM}	Charged device model	500	V
	Charged device model for PLL power pins and dedicated clocks 1, 3, 9, and 11	300	V

Power Consumption

Designers can calculate the power usage for their design using the Altera power calculator and the simulation-based power estimation feature in the Quartus® II software.

The interactive power calculator is typically used prior to designing the FPGA in order to get a magnitude estimate of the device power. The Quartus II software simulation-based power estimation feature allows designers to apply test vectors against their design for more accurate power consumption modeling.

In both cases, these calculations should only be used as an estimation of power, not as a specification.

Contact Altera Applications for information on the Cyclone II power calculator.

Cyclone II devices require a certain amount of power-up current to successfully power up because of the nature of the leading-edge process on which they are fabricated. Table 5–14 will show the maximum power-up current required to power up a Cyclone II device after device characterization has been performed.

Table 5–14. Cyclone II Power-Up Current (I_{CCINT}) Requirements

Device	Maximum Power-Up Current Requirement	Unit
EP2C5	*(1)*	mA
EP2C8	*(1)*	mA
EP2C20	*(1)*	mA
EP2C35	*(1)*	mA
EP2C50	*(1)*	mA
EP2C70	*(1)*	mA

Note to Table 5–14:
(1) This specification will be available in a future version of the data sheet.

Designers should select power supplies and regulators that can supply this amount of current when designing with Cyclone II devices. This specification is for commercial operating conditions. Measurements were performed with an isolated Cyclone II device on the board. Decoupling capacitors were not used in this measurement. To factor in the current for decoupling capacitors, sum up the current for each capacitor using the following equation:

$$I = C (dV/dt)$$

The exact amount of current that will be consumed varies according to the process, temperature, and power ramp rate. The duration of the I_{CCINT} power-up requirement depends on the V_{CCINT} voltage supply rise time.

Altera recommends using the Cyclone II Power Calculator to estimate the user-mode I_{CCINT} consumption and then select power supplies or regulators based on the higher value.

Timing Specifications

The DirectDrive™ technology and MultiTrack™ interconnect ensure predictable performance, accurate simulation, and accurate timing analysis across all Cyclone II device densities and speed grades. This section describes and specifies the performance, internal, external, and PLL timing specifications.

This section shows the timing models for Cyclone II devices. Commercial devices will meet this timing over the commercial temperature range. Industrial devices will meet this timing over the industrial temperature range. All specifications are representative of worst-case supply voltage and junction temperature conditions.

The preliminary timing model will be added into a future revision of this Data Sheet.

Preliminary & Final Timing Specifications

Timing models can have either preliminary or final status. The Quartus II software issues an informational message during the design compilation if the timing models are preliminary. Table 5–15 shows the status of the Cyclone II device timing models.

Preliminary status means the timing model is subject to change. Initially, timing numbers are created using simulation results, process data, and other known parameters. These tests are used to make the preliminary numbers as close to the actual timing parameters as possible.

Final timing numbers are based on actual device operation and testing. These numbers reflect the actual performance of the device under worst-case voltage and junction temperature conditions.

Table 5–15. Cyclone II Device Timing Model Status

Device	Preliminary	Final
EP2C5	✓	
EP2C8	✓	
EP2C20	✓	
EP2C35	✓	
EP2C50	✓	
EP2C70	✓	

PLL Timing Specifications

Table 5–16 describes the Cyclone II PLL specifications when operating within the commercial junction temperature range from 0° to 85° C.

PLL specifications under industrial temperature-range operating conditions are pending silicon characterization. The industrial junction temperature range specifications will be available upon completion of the PLL characterization across the industrial junction temperature range from -40 to 100° C.

Table 5–16. PLL Specifications *Note (1)*

Symbol	Parameter	Min	Max	Unit
f_{IN}	Input frequency (-6 speed grade)	11	311	MHz
	Input frequency (-7 speed grade)	11	270	MHz
	Input frequency (-8 speed grade)	11	240	MHz
f_{IN} DUTY	Input clock duty cycle	40	60	%
t_{IN} JITTER	Input clock period jitter		200	ps
f_{OUT_EXT} (external PLL clock output)	PLL output frequency (-6 speed grade)	15.625	*(4)*	MHz
	PLL output frequency (-7 speed grade)	15.625	*(4)*	MHz
	PLL output frequency (-8 speed grade)	15.625	*(4)*	MHz
f_{OUT} (to global clock)	PLL output frequency (-6 speed grade)	10	402.5	MHz
	PLL output frequency (-7 speed grade)	10	350	MHz
	PLL output frequency (-8 speed grade)	10	310	MHz
t_{OUT} DUTY	Duty cycle for external clock output (when set to 50%)	45	55	%
t_{JITTER} *(2)*	Period jitter for external clock output			ps
t_{LOCK}	Time required to lock from end of device configuration		1	ms
f_{VCO} *(3)*	PLL internal VCO operating range	300	1,000	MHz

Notes to Table 5–16:

(1) These numbers are preliminary and pending silicon characterization.

(2) The t_{JITTER} specification for the `PLL[2..1]_OUT` pins are dependent on the I/O pins in its `VCCIO` bank, how many of them are switching outputs, how much they toggle, and whether or not they use programmable current strength.

(3) If the design enables divide by 2, a 300- to 499-MHz internal VCO frequency is available.

(4) This parameter is limited in Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

High Speed I/O Timing Specifications

Since LVDS, mini-LVDS, and RSDS data communication is source synchronous, timing analysis is different than other I/O standards. The high-speed I/O signal is based on skew between the data and the clock signal.

Designers should also consider board skew, cable skew, and clock jitter in their calculation. This section provides details on high-speed I/O standards timing parameters in Cyclone II devices.

Table 5–17 defines the parameters of the timing diagram shown in Figure 5–3.

Table 5–17. High-Speed I/O Timing Definitions

Parameter	Symbol	Description
High-speed I/O data rate	HSIODR	High-speed receiver and transmitter input and output data rate.
Period	TUI	Time unit interval. TUI = 1/HSIODR.
Channel-to-channel skew	TCCS	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew. The clock is included in the TCCS measurement. TCCS = TUI – SW – (2 × RSKM)
Sampling window	SW	The period of time during which the data must be valid in order for you to capture it correctly. Sampling window is the sum of the setup time, hold time, and jitter. The window of t_{SU} + t_H is expected to be centered in the sampling window. SW = TUI – TCCS – (2 × RSKM)
Receiver input skew margin	RSKM	RSKM is defined by the total margin left after accounting for the sampling window and TCCS. The RSKM equation is: RSKM = (TUI – SW – TCCS) / 2

Figure 5–3. High-Speed I/O Timing Diagram

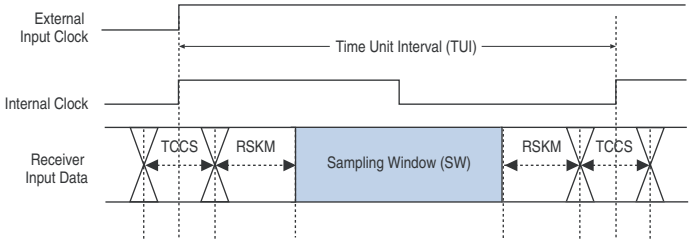
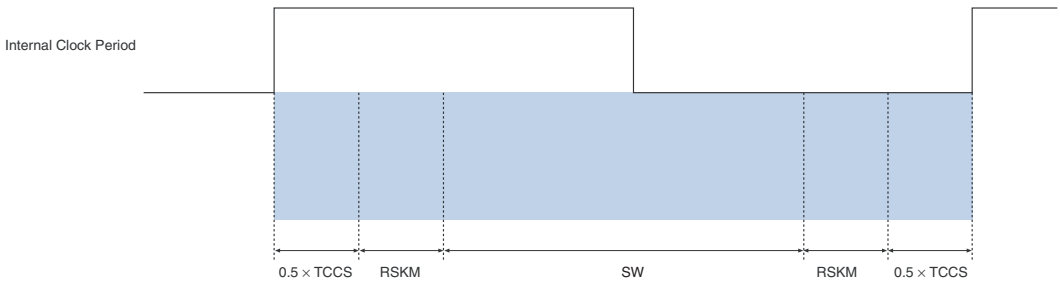


Figure 5–4 shows the high-speed I/O timing budget.

Figure 5–4. High-Speed I/O Timing Budget *Note (1)*



Note to Figure 5–4:

(1) The equation for the high-speed I/O timing budget is:
period = TCCS + RSKM + SW + RSKM.

Table 5–18 shows the RSDS timing budget for Cyclone II devices at 170 Mbps. RSDS is supported for transmitting from Cyclone II devices. Cyclone II devices can not receive RSDS data because the devices are intended for applications where they will be driving display drivers.

Cyclone II devices support a maximum RSDS data rate of 170 Mbps using DDIO registers. The maximum internal clock frequency when designing for RSDS is 85 MHz.

Table 5–18. RSDS Transmitter Timing Specification

Symbol	Conditions	-6 Speed Grade			-7 Speed Grade			-8 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
HSIODR	Using DDIO registers *(1)*	31.25		170	31.25		170	31.25		170	Mbps
Period		5.88			5.88			5.88			ns
TCCS				1.68			1.68			1.68	ns
SW	*(2)*			4.00			4.00			4.00	ns
RSKM	*(3)*			0.10			0.10			0.10	ns

Notes to Table 5–18:

(1) The minimum data rate is limited by 2 × f_{IN}(minimum) for the PLL specifications shown in Table 5–16.

(2) This is how large the sampling window (sum of t_{SU}, t_H, and t_{JITTER}) can be at the receiving device. The Cyclone II device is a transmitter only for the RSDS I/O standard.

(3) The RSKM is assumed to be 100 ps for a calculated sampling window. RSKM is a system parameter determined by the designer.

In order to determine the transmitter timing requirements, RSDS receiver timing requirements on the other end of the link must be taken into consideration. RSDS receiver timing parameters are typically defined as t_{SU} and t_H requirements. Therefore, the transmitter timing parameter specifications are t_{CO} (minimum) and t_{CO} (maximum). Refer to Figure 5–4 for the timing budget.

The AC timing requirements for RSDS are shown in Figure 5–5.

Figure 5–5. RSDS Transmitter Clock to Data Relationship

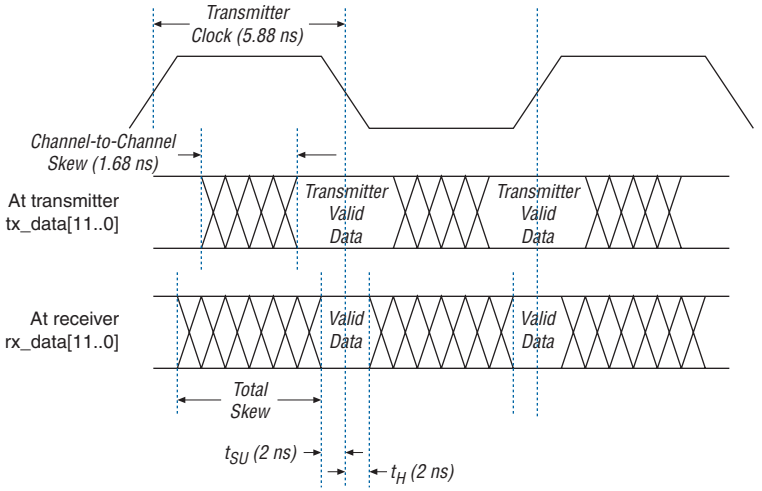


Table 5–19 shows the mini-LVDS transmitter timing budget for Cyclone II devices at 170 Mbps. Cyclone II devices can not receive mini-LVDS data because the devices are intended for applications where they will be driving display drivers. A maximum mini-LVDS data rate of 170 Mbps is supported for Cyclone II devices using DDIO registers. The maximum internal clock frequency when designing for mini-LVDS is 85 MHz.

Table 5–19. mini-LVDS Transmitter Timing Specification

Symbol	Conditions	-6 Speed Grade			-7 Speed Grade			-8 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
HSIODR	Using DDIO registers *(1)*	31.25		170	31.25		170	31.25		170	Mbps
Period		5.88			5.88			5.88			ns
TCCS				0.388			0.388			0.388	ns
SW	*(2)*			5.292			5.292			5.292	ns
RSKM	*(3)*			0.10			0.10			0.10	ns

Notes to Table 5–19:

(1) The minimum data rate is limited by 2 × f_{IN}(minimum) for the PLL specifications shown in Table 5–16.

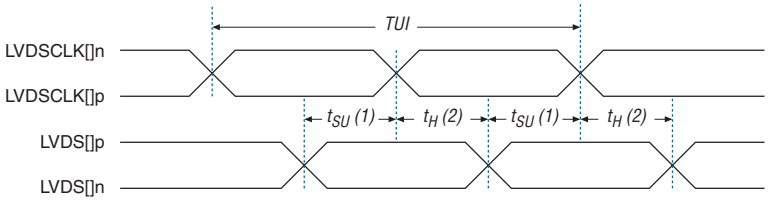
(2) This is how large the sampling window (sum of t_{SU}, t_H, and t_{JITTER}) can be at the receiving device. The Cyclone II device is a transmitter only for mini-LVDS.

(3) RSKM assumed to be 100 ps for calculated SW. RSKM is a system parameter determined by the designer.

In order to determine the transmitter timing requirements, mini-LVDS receiver timing requirements on the other end of the link must be taken into consideration. mini-LVDS receiver timing parameters are typically defined as t_{SU} and t_H requirements. Therefore, the transmitter timing parameter specifications are t_{CO} (minimum) and t_{CO} (maximum). Refer to Figure 5–4 for the timing budget.

The AC timing requirements for mini-LVDS are shown in Figure 5–6.

Figure 5–6. mini-LVDS Transmitter AC Timing Specification



Notes to Figure 5–6:
(1) The data setup time, t_{SU}, is 0.225 × TUI.
(2) The data hold time, t_H, is 0.225 × TUI.

Table 5–20 shows the LVDS timing budget for Cyclone II devices. Cyclone II devices support LVDS receivers at data rates up to 805 Mbps and LVDS transmitters at data rates up to 622 Mbps.

Table 5–20. LVDS Timing Specification

Symbol	Conditions	-6 Speed Grade			-7 Speed Grade			-8 Speed Grade			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
HSIODR *(1)*	10	156.25		622	156.25		622	156.25		530	Mbps
	8	125		622	125		622	125		530	Mbps
	7	125		622	125		622	125		530	Mbps
	4	62.5		622	62.5		622	62.5		530	Mbps
	2	31.25		622	31.25		622	31.25		530	Mbps
	1 *(2)*	15.625		311	15.625		311	15.625		265	Mbps
Period		1.608			1.608			1.886			ns
TCCS				200			200			230	ps
SW *(3)*		800			800			920			ps
RSKM				304			304			368	ps

Notes to Table 5–20:

(1) The minimum data rate is limited by 2 × f_{IN}(minimum) for the PLL specifications shown in Table 5–16.

(2) The PLL must divide down the input clock frequency to have the internal clock frequency meet the specification shown in Table 5–16.

(3) These values assume 400 ps of PLL jitter for the SW parameter.

Chapter 6. Reference & Ordering Information

CII51006-1.1

Software

Cyclone™ II devices are supported by the Altera® Quartus® II design software, which provides a comprehensive environment for system-on-a-programmable-chip (SOPC) design. The Quartus II software includes HDL and schematic design entry, compilation and logic synthesis, full simulation and advanced timing analysis, SignalTap® II logic analyzer, and device configuration. See the *Quartus II Handbook* for more information on the Quartus II software features.

The Quartus II software supports the Windows XP/2000/NT/98, Sun Solaris, Linux Red Hat v7.1 and HP-UX operating systems. It also supports seamless integration with industry-leading EDA tools through the NativeLink® interface.

Device Pin-Outs

Device pin-outs for Cyclone II devices are available on the Altera web site (**www.altera.com**). For more information contact Altera Applications.

Ordering Information

Figure 6–1 describes the ordering codes for Cyclone II devices. For more information on a specific package, contact Altera Applications.

Figure 6–1. Cyclone II Device Packaging Ordering Information